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Revision History

Janguard

General Description

V98XX is a single-phase energy metering SoC chip, featuring very low power consumption and high performance. It integrates Analog Front-End (AFE), energy metering architecture, enhanced 8052 MCU core, RTC, WDT, Flash memory, RAM, and LCD driver. It can be used for the single-phase multi-functional energy meter applications.

Features

- Optional power supply 3.3 V or 5 V, wide input range: 2.5 V to 5.5 V
- Reference voltage: 1.185 V (Typical drift) 10 ppm/°C), interrupt triggered by external capacitor leakage - Optional power supply 3.3 V or 5 V, wide

input range of 3000:1

Neference voltage: 1.185 V (Typical drift

10 pm/ⁿC), internut tingered by

external capacitor leakage

external capacitor leakage

external capacitor
- Typical current load in full operation mode: 5.5 mA
- Typical current load in sleeping mode: 10 μA
- Supporting anti-tampering energy metering application
- Operating temperature: -40 °C \sim +85 °C
- Storage temperature: -55 °C \sim +150 °C
- Energy metering features:
	- Four independent oversampling Σ/Δ ADCs
		- \checkmark One voltage channel
		- Two current channels, supporting shunt or CT for current sensing
		- \checkmark One multifunctional channel for various signal measurements
	- High metering accuracy:
		- Exceeding requirements of IEC 62053-21:2020/ IEC 62053- 22:2020 and IEC 62053- 23:2020
		- \checkmark Less than 0.1% error on active energy metering over dynamic range of 5000:1
			- Less than 0.1% error on reactive

energy metering over dynamic range of 3000:1

- Less than 0.5% error on current/voltage RMS calculation over dynamic range of 1000:1
- Various measurements:
	- Raw waveform and DC component of current and voltage signals
	- Instantaneous/Average and active/reactive power
	- Positive/Negative and active/reactive energy
	- Average apparent power
	- \checkmark Instantaneous/Average current and voltage RMS
	- Line frequency
	- Temperature with measurement accuracy of ±1°C
	- Battery voltage and external voltage signals
- Two current inputs for active energy metering, or one current input for active and reactive energy metering
- Programmable energy metering modes:
	- Accumulating power, current RMS, or a constant for energy metering
	- Accumulating energy at a

configurable frequency

- Calibrating meters via software:
	- Phase compensation over a range of $\pm 1.4^{\circ}$ (min.), resolution of 0.0055°/lsb (min.).
	- \checkmark Gain calibration of RMS and power, and offset calibration of power
	- \checkmark Accelerating meter calibration when low current is applied
- CF pulse output and interrupt with configurable pulse width
- Zero-crossing interrupt
- Speeding current detection to lower power consumption
- Programmable threshold for no-load detection
- MCU and peripherals:
- High performance 8-bit 8052 MCU core, with programmable operation frequency, up to 26 MHz/6.5 mips A core eration meter cellibration over the content of the specified content is appled to the CPI (See all the CPI compliant content of the CPI compliant of the CP
	- One additional comparator
	- Integrated oscillator, only one external 32768-Hz crystal is needed to generate crystal frequency
	- Crystal supervised: Internal RC oscillator as a replacement when crystal oscillator stops running
	- Integrated RTC and temperature sensor, digital crystal frequency compensation for calibration over temperature variation

128-KB Flash memory, ISP and IAP supported, with write protection and encryption function

- 4-KB extended SRAM memory
- Up to five UART serial interfaces, one supporting IR communication
- Up to two enhanced UART (EUART) serial interfaces, ISO/IEC 7816-3 compliant
- One GPSI (General-Purpose Serial Interface), I²C compliant
- Up to 54 programmable GPIOs, with port interrupt
- Up to 16 fast IOs
- Up to 12 hardware timers
- Supporting PWM output
- LCD driver:
	- Up to 4×40, 6×38, or 8×36 segments
	- 1/3 bias or 1/4 bias ratio
	- \checkmark Configurable frame frequency
	- Configurable drive voltage over a range of 2.7 V \sim 3.3 V, resolution 100 mV/lsb
- Various sleep/wakeup methods, configurable wakeup with reset
- Independent Watch-Dog Timer (WDT)
- Debugging via JTAG interfaces in real-time

V98XX Resource Comparison

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Table List

1.Electrical Characteristics

1.1. Absolute Maximum Ratings

Operating circumstance exceeding **"Absolute Maximum Ratings"** may cause the permanent damage to the device.

Table 1-1 Absolut Maximum Ratings

1.2. Energy Metering Specifications

All typical specifications are at TA = 25 °C, VDD5 = 5.0 V $\pm 10\%$, and fMTCLK = 3.2768 MHz, unless otherwise noted.

Table 1-2 Energy Metering Specifications

1.3. Analog Specifications

All maximum and minimum specifications apply over the entire recommended operation range (T = -40 °C ~ +85 °C, VDD5 = 3.3 V or 5.0 V), unless otherwise noted. All typical specifications are at TA = 25 °C and VDD5 = 5.0 V \pm 10%, unless otherwise noted.

Table 1-3 Analog Specifications

Power-Down Detection Threshold ("VDCIN")

1.4. Digital Interface Specifications

All maximum and minimum specifications apply over the entire recommended operation range (T = -40 °C \sim +85 °C, VDD5 = 3.3 V or 5.0 V), unless otherwise noted.

Table 1-4 Digital Interface Specifications

1.5. Memory Specifications

All maximum and minimum specifications apply over the entire recommended operation range (T = -40 °C ~ +85 °C, VDD5 = 3.3 V or 5.0 V), unless otherwise noted. All typical specifications are at TA = 25 °C, VDD5 = 5.0 V \pm 10% or f_{MCU} = 13.1072 MHz, unless otherwise noted.

Table 1-5 Memory Specifications

1.6. GPSI Timing Specifications

All maximum and minimum specifications apply over the entire recommended operation range (T = -40 °C \sim +85 °C, VDD5 = 3.3 V or 5.0 V ±10%), unless otherwise noted.

Table 1-6 GPSI Timing Specifications

1.7. Typical Operating Current

Table 1-7 Typical Operating Current

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2.Pin Descriptions

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Figure 2-1 Pin Assignment

3.Functional Block Diagram

*1.2V REF_LP represents the low power reference voltage unit (not the BandGap circuit). This unit works all the time until the chip is powered off. This unit provides the 3.3V LDO and digital power supply with 1.2V reference voltage, and it can be the negative input for the comparator CB.

^{*1.2}V REF_LP represents the low power reference voltage unit (not the BandGap circuit). This unit works all the time until the chip is powered off. This unit provides the 3.3V LDO and digital power supply with 1.2V reference voltage, and it can be the negative input for the comparator CB.

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*1.2V REF_LP represents the low power reference voltage unit (not the BandGap circuit). This unit works all the time until the chip is powered off. This unit provides the 3.3V LDO and digital power supply with 1.2V reference voltage, and it can be the negative input for the comparator CB.

4.8052 MCU Core Architecture

4.1. Memory Map

V98XX contains three memory blocks:

- 256 bytes of internal SRAM (IRAM), sharing the upper 128 bytes of its addresses with Special Function Registers (SFRs).
- 4-KB internal extended RAM (XRAM) and the memory of peripherals sharing the data memory area at addresses **"0000h" ~ "FFFFh"**.
- 128-KB on-chip Flash memory mapping the program memory area at addresses **"0000h" ~ "FFFFh".**

4.2. IRAM (Internal RAM) and SFRS (Special Function Registers)

The 256-byte internal SRAM (IRAM), located at addresses **"00h" ~ "FFh"**, is composed of two parts: the lower 128-byte RAM and the upper 128-byte RAM. When the output voltage of **"DVCC"** is higher than

1.62 V, IRAM holds the data in it even when MCU is reset to its default state.

The lower 128-byte internal RAM contains three distinct blocks: Register Bank 0~3 (**"00h" ~ "1Fh"**), Bit Address Area (**"20h" ~ "2Fh"**) and General RAM Area (**"30h" ~ "7Fh"**). All the lower 128-byte internal RAM can be accessed by direct or indirect addressing.

- Register Bank 0~3, 32 bytes from **"00h"** to **"1Fh"**, each is composed of 8 registers, R0~R7. Users can configure **"bit4"** (**"RS1"**) and **"bit3"** ("**RS0"**) of the register **"PSW"** (SFR 0xD0, Program Status Word SFR) to select the register bank to be used. By default Register Bank 0 is used.

- Bit Address Area (**"20h" ~ "2Fh"**), each with bit addresses from **"00h"** to **"7Fh"**, is bit addressable.

- General RAM, from **"30h"** to **"7Fh"**, can be addressed directly.

The upper 128-byte internal RAM, located at addresses **"80h" ~ "FFh",** shares its addresses with a group of specific internal registers (Special Function Registers, SFRs), but they are accessed in different

ways. SFRs are accessed via direct addressing, but the upper 128-byte internal RAM is accessed via indirect addressing.

Figure 4-1 IRAM and SFR

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4.3. Data Memory

4096 bytes of XRAM and peripherals registers can be mapped to the data storage space. XRAM is located at addresses **"0000h" ~ "0FFFh"** that can be accessed limitless. The content of XRAM cannot be reset by any reset event, and it will hold the data in it until the output voltage of **"DVCC"** is lower than

1.62 V.

The bytes located at addresses **"0x3000" ~ "0x33FF"**, (Info area, read) are designed to store recommended configuration for analog registers , parameters for temperature measurement, and RTC calibration that are pre-programmed by Vango when the chips are being manufactured, see [Figure 4-2](#page-52-0) for details. The program can access the information within the address range in the same way as

accessing the peripheral registers.

In Data storage space, in addition to the contents of the XRAM and Info area, all of the peripherals registers can be reset. Among them, the LCD/GPIO simulation control/registers related energy metering can only be reset and are set to the default values by the Level 1 reset, other registers will be reset to the default values by the Level 1/2/3 reset. The contents of the Info area will not be reset, after a reset event of Level 1, the content of these bytes will be settled in 2 ms, and then CPU can execute the programs in Flash memory. These bytes are readable only, and MCU can read of these bytes as they are peripherals.

Figure 4-2 Data Memory

Table 4-3 Allocation of Info Area

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*Users can read of these bytes and obtain the recommended configuration of the analog control registers, and then write them to the analog control registers.

See **"[Measuring Temperature](#page-124-0)" for details of parameter A, B, C, D, E, and temperature error.

***When users are using the crystals provided by Vango, they can read these addresses to obtain the details of crystal frequency deviation Δ, parabolic coefficient Bpara, and turnover temperature of the crystal, to calibrate RTC. See the corresponding application notes for details.

4.4. Program Memory

In V98XX, the 128-KB on-chip Flash memory (Including program encryption bytes) and the Flash control registers are mapped to the MCU program memory at addresses **"0000h" ~ "FFFFh".** The Flash control registers mapped to the MCU program memory at addresses **"0x0401"** and **"0x0402"**, determining the programming mode and power consumption mode of the Flash memory.

Table 4-4 Flash Control Register 1 (FCtrl1, 0x0402)

Figure 4-3 Flash Memory and Program Memory Area

The 128-KB on-chip Flash memory of V98XX is featured with write protection, program encryption, and ISP (In-System Programming), and IAP (In-Application Programming) supported.

The 8052 MCU core of V98XX can address up to 64-KB program memory area, **"0000h" ~ "FFFFh"**, but the Flash memory can store up to 128-KB codes. So to execute more than 64-KB program, the code banking technique should be used. Using this technique, the program can be divided into no more than four parts with no more than 64-KB codes each, and is allocated in different parts of the Flash memory:

- **"Common Area"**, at addresses **"0000h" ~ "7FFFh"**: To allocate the common codes, such as interrupt vectors, reset vectors, bank switching routines, interrupt service routines, and so on. It is always mapped to the program memory area at addresses **"0000h" ~ "7FFFh"**.
- **"Code Area"**, at addresses **"8000h" ~ "1FFFFh"**: To allocate the application codes; Bank 1, at addresses **"8000h" ~ "FFFFh"**; Bank2, at addresses **"10000h" ~ "17FFFh"**; Bank 3, at addresses **"18000h" ~ "1FFFFh"**. **Each bank can be mapped to the program memory area at addresses "8000h" ~ "FFFFh",** and the processor can access the register **"CBANK"** (SFR 0xA0) to switch the banks and execute the codes.

Table 4-5 Code Bank Register (CBANK, SFR 0xA0)

In V98XX, the on-chip Flash memory is divided into 256 pages with 512 bytes each. The codes in the Flash memory can be read, erased, or programmed in pages or mass erased.

Notes: The third page of the Flash memory, at addresses **"0400h" ~ "05FFh"**, is pre-programmed with codes by the manufacturer, so this part cannot be used for application codes.

When the low logic level is input on the pin **"MODE1"**, the chip will be in the debugging mode. In this mode, the 4 pins of Group P0 work as JTAG interfaces. Users can use the DLL codes and simulators provided by Vango to download and debug the applications in Keil μVision IDE or IAR IDE via the JTAG interfaces.

Notes:

Please comment the lines, like switching the system clock source from PLL clock to OSC clock, and get to sleep, out of the codes.

In the debugging mode, the system cannot get to **"Sleep"** or **"Deep Sleep"**, and the reset events, POR/BOR and WDT overflow, are masked. In the sleeping state, a power recovery event will occur immediately once the system goes to the debugging mode.

In the debugging mode, the TCK speed limit is 400 Kbps by default. The command **"0x22"** can increase it to the current PLL clock frequency, and the command **"0x23"** can recover it.

No capacitors should be connected to the JTAG interfaces to avoid the download failure of codes.

There is an encryption bit (**"bit0"** of byte located at address **"0x0400"**) in the Flash memory. The configuration of this bit has effect on the access to the Flash memory. When the high logic level is input on the pin **"MODE1"**, the chip will be in the metering mode. In this mode, the on-chip Flash memory is IAP supportive, and the access to the Flash memory will not be affected by the encryption bit configuration. When the low logic level is input on the pin **"MODE1"**, the chip will be in the metering mode. In this mode, the on-chip Flash memory is IAP and ISP supportive, and the encryption bit configuration will affect the access to the Flash memory. 1.1.01 ex 1.1.05 1

10: Bank 2;

11: Bank 2;

11: Bank 2;

11: Bank 3.

11: Bank 3:

11: Bank 3:

11: Bank 3:

11: Bank 3:

11: Ba

Table 4-6 Programming Flash Memory

Note: After ISP, the input logic low to the pin **"RSTn"** or power on the chip again to activate the ISP read encryption.

4.5. Instruction Set

The instruction set of the enhanced 8052 core is compatible with the industry standard 8051 MCU in binary code and the execution results are functionally equivalent. However, the number of clock cycles that each instruction cycle needs is different from that of the standard 8051 instruction set. And the execution timing of each instruction is also different from that of standard 8051 MCU. Each instruction cycle has four clock cycles.

Table 4-7 Instruction Set

4.5.1. Programmable MOVX Timing

The programmable MOVX timing feature enables application to adjust the speed of the access to the data memory. CPU can execute the MOVX instruction in as little as two instruction cycles. However, it is sometimes desirable to stretch this value. **"Bit2" ~ "bit0"** (MD2~0) of **"CKCON"** (SFR 0x8E) control the stretch value, which can set the stretch value from **'0'** to **'7'**. A stretch value of **'0'** means no extra instruction cycles are added and the MOVX instructions will be executed in two instruction cycles. A stretch value of **'7'** means additional seven instruction cycles are added, and the MOVX instructions will

be executed in nine instruction cycles. The stretch value is programmable. The stretch value will affect the width of the read/write strobe and all related timing. A higher stretch value results in a wider read/write strobe. By default the stretch value is **'1'**, meaning three instruction cycles are needed to execute the MOVX instruction.

Table 4-8 Programmable MOVX Timing

4.5.2. Dual Data Pointers

Dual data pointers, standard data pointer **"DPTR0"** located at addresses **"SFR 0x82"** and **"SFR 0x83"**, and the second data pointer **"DPTR1"** located at addresses **"SFR 0x84"** and **"SFR 0x85"**, can improve the efficiency significantly when moving large blocks of data. The bit **"SEL"** (bit0) in the DPTR Select Register (DPS, SFR 0x86) is configured to select the active pointer. When **"SEL"** is cleared, **"DPL0"** (SFR 0x82) and **"DPH0"** (SFR 0x83) are selected. When **"SEL"** is set to **'1', "DPL1"** (SFR 0x84) and **"DPH1"** (SFR 0x85) are selected.

All DPTR-related instructions use the selected data pointer. Rewrite of the bit **"SEL"** to switch the pointer. The fastest way to do so is to use the increment instruction (INC DPS). Only one instruction is required to switch from the source address to the target address. When doing a block move, it is no need to save source and target addresses, which saves the number of application codes.

5.Reset

In V98XX, all circuits, except for the RTC calibration registers, RTC timing registers, IRAM, XRAM, and Info area, can be reset to their default states by an event of a specific reset level. Three levels of events are designed to reset different circuits of the system. They are:

- **Level 3:** The lowest level, including the debugging reset instruction. When the event of this level occurs, CPU, interrupt management circuits, timers, UART interfaces, and GPSI interfaces will be reset to their default states.
- **Level 2:** Including the power recovery (Power up), IO wakeup event, RTC wakeup event, and CF pulse wakeup event.

When an event of this level occurs, **"Clock Switchover Control Register"** (**"SysCtrl"**, SFR 0x80), **"IO Wakeup Control Register"** (**"IOWK"**, SFR 0xC9), **"IO Wakeup Edge Control Register"** (**"IOEDG"**, SFR 0xC7), Flash control registers, watch-dog timer, and all the circuits that can be reset by events of Level 3 will be reset to their default states.

 Level 1: The highest level, including the RSTn pin input signal (RSTn pin reset), power-on reset (POR), brown-out reset (BOR), and WDT overflow event. When an event of this level occurs, the LCD driver, general-purpose I/O ports, **"System State Register"** (**"Systate"**, SFR 0xA1), **"P0 IO Wakeup Flag Register"** (**"IOWKDET"**, SFR 0xAF), analog control registers, the global energy metering architecture, and all the circuits that can be reset by events of Level 2 will be reset to their default states.

In V98XX, the reset management circuits are designed by following the rule that a reset event of higher level can reset the circuits that can be reset by a reset event of lower level, but not *vice versa*.

5.1. Level 3

In V98XX, only the debugging reset instruction is designed as the reset event of Level 3. It can reset CPU, interrupt management circuits, timers, UART interfaces, and GPSI interfaces.

When **"logic 0"** is input to the pin **"MODE1"**, the system will enter the debugging mode. In this mode, when the debugging operation is enabled or the tab **"Reset"** in IDE is clicked, a debugging reset instruction will be executed to reset CPU and its peripherals.

5.2. Level 2

In V98XX, power recovery, IO wakeup event, RTC wakeup event, and CF pulse wakeup event are designed as the reset events of Level 2.

By default, any event of this level can wake up the system from **"Sleep"** or **"Deep Sleep"** and reset the system to OSC state. But if the bit **"IORSTN"** (**"bit0"** of **"IOWK**", SFR 0xC9) is set to **'1'**, any event of this level can wake up the system without reset, after wakeup, CPU keeps on executing programs; all circuits go back where the system enters the sleeping state, but **"bit[2:1]"** (**"SLEEP1"** and **"SLEEP0"**) and **"bit[6:5]"** (**"FWC"** and **"FSC"**) are cleared.

When **"IORSTN"** (**"bit0"** of **"IOWK"**, SFR 0 xc9) is cleared, in addition to the reset circuit which can be reset by Level 3 reset events, the wakeup events can reset the clock switch control register (**"SysCtrl"**, SFR 0 x80), IO dormancy awakening edge selection register (**"IOEDG"**, SFR 0 xc7), IO dormancy awakened control register (**"IOWK"**, SFR 0 xc9), FLASH control registers and WDT, please refer to [V](#page-65-0)98XX, only the debugging reset instruction is designed as the reset event of Level 3. It can

, interrupt management circuits, timers, UART interfaces, and GPSI interfaces

hen "logic O" is input to the pin "MODE1", the s

Figure 5-1 for more detailed information.

5.2.1. Power Recovery (Power up)

In V98XX, when the voltage on the pin **"VDCIN"** rises from lower than 1.0 V to higher than 1.1 V, or when the voltage on the pin **"VDCIN"** is higher than 1.1 V after any reset event of Level 1, a power recovery event will occur. By default, this event wakes up the chip and resets it to the OSC state, and the reset signal holds 8 OSC clock cycles (About 244 μs). To lower the power consumption, users can set the bit **"IORSTN"** (**"bit0"** of **"IOWK"**, SFR 0xC9) to **'1'** to wake up the system without reset.

5.2.2. IO Wakeup Event

In V98XX, 4 pins, **"WAKEUP1 (P1.4)", "WAKEUP2 (P1.3)", "WAKEUP3 (P0.2)",** and

"WAKEUP4 (P0.3)" can be used to wake up the chip from **"Sleep"** or **"Deep Sleep"**. Pins **"WAKEUP1"** and **"WAKEUP2"** can be used for the wakeup input all the time, but pins **"WAKEUP3"** and **"WAKEUP4"** can be used for the wakeup input only when the bit **"IOP0"** (**"bit1"** of **"IOWK"**, SFR 0xC9) is set to **'1'.** The wakeup input on these four I/O ports are independent.

If the four I/O ports are set to **"Input enabled"** before the chip enters **"Sleep"** or **"Deep Sleep"**, a transition (Either **"high-to-low"** or **"low-to-high"**, with more than four OSC clock cycles on both levels) on the pin in **"Sleep"** or **"Deep Sleep"** can wake up the system. Users can configure the register **"IOEDG"** (SFR 0xC7) to determine the active edge for the IO wakeup event. Any IO wakeup event can set the bit "IO" ("bit3" of "Systate", SFR 0xA1) to '1'. When the bit "IO" is set to '1', users can read bits **"P14WK"**, **"P02WK",** and **"P03WK"** (**"bit[0:2]"** of **"IOWKDET"**, SFR 0xAF) to detect that the system is woken up by the transition on which pin.

By default, a transition on any one of the four I/O ports can wake up the system and reset it to the OSC state. To lower the power consumption, users can set the bit **"IORSTN"** (**"bit0"** of **"IOWK"**, SFR 0xC9) to **'1'** to wake up the system without reset.

5.2.3. RTC Wakeup Event

In V98XX, RTC can wake up the system from **"Sleep"** at an interval set in registers **"INTRTC"** (SFR 0x96) and **"SECINT"** (SFR 0xDF). When the system is woken up by an RTC event, the bit **"RTC/CF"** (**"bit2"** of **"Systate"**, SFR 0xA1) will be set to **'1'**, but the bit **"CFWK"** (**"bit3**" of **"IOWKDET"**, SFR 0xAF) will be cleared. Please refer to Figure 5-1 for more detailed information.

By default, RTC wakeup event can wake up the system from **"Sleep"** and reset it to the OSC state. The reset signal holds 8 OSC clock cycles. To lower the power consumption, users can set the bit **"IORSTN"** (**"bit0"** of **"IOWK**", SFR 0xC9) to **'1'** to wake up the system without reset.

5.2.4. CF Pulse Wakeup Event

In V98XX, the system may be woken up from **"Sleep"** by CF pulse output, if CF pulse output is enabled (**"CFENR"** = **'1'** or **"CFEN"** = **'1'**, **"bit[5:4]"** of **"PMCtrl4"**, 0x287D), and CF pulse output is enabled to be a wakeup event (**"CFWKEN"** = **'1'**, **"bit2"** of **"IOWK"**, SFR 0xC9) before the system enters **"Sleep".** When a CF pulse wakeup event occurs, both bits **"RTC/CF"** (**"bit2"** of **"Systate"**, SFR 0xA1) and **"CFWK"** (**"bit3"** of **"IOWKDET"**, SFR 0xAF) are set to 1s. "P14WK", "PD2WK", and "PD3WK" ("bit[0:2]" of "IOWKDET", SFR 0xAF) to detect tha

em is woken up by the transition on which pin.

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By default, a CF pulse wakeup event can wake up the system from **"Sleep"** and reset it to the OSC state. To lower the power consumption, users can set the bit **"IORSTN"** (**"bit0"** of **"IOWK",** SFR 0xC9) to **'1'** to wake up the system without reset.

5.3. Level 1

In V98XX, WDT overflow, RSTn pin input signal, Power-On Reset (POR), and Brown-Out Reset (BOR) are designed as the reset events of Level 1. When any one of these reset events occurs, the bit **"POR"** (**"bit5"** of **"Systate"**, SFR 0xA1) will be set to **'1'**.

5.3.1. RSTn Pin Reset

Holding logic low on the pin **"RSTn"** for more than 5 ms can trigger an RSTn pin reset signal to reset the system. After the logic is pulled high, the reset signal holds four more OSC clock cycles (About 122 μs) and then is released.

To prevent from the static disturbance, the input signal on the pin **"RSTn"** is filtered basing on the RC clock.

Figure 5-2 RSTn Pin Reset Timing

5.3.2. Power-On Reset (POR) and Brown-Out Reset (BOR)

In V98XX, the output voltage of the digital power supply (Via pin **"DVCC"**) is monitored by the power-on/brown-out reset circuit.

On power-up, a power-on reset signal will be generated to reset the system when the output voltage of pin **"DVCC"** is lower than 1.4 V. The system will stay in the reset state for four OSC clock cycles (About 122 μs) even when the voltage on the pin **"DVCC"** is higher than 1.4 V.

On power-down, when the output voltage on the pin **"DVCC"** is lower than 1.4 V, the brown-out reset circuit will generate a reset signal to reset the system.

When **"logic 0"** is input to the pin **"MODE1"**, POR/BOR will be masked.

Figure 5-3 POR/BOR Timing

5.3.3. WDT Overflow Reset

In V98XX, when the WDT overflows, a reset signal will be generated and the system will be reset. The system will exit from the reset state in eight RC clock cycles (About 250 μs).

When **"logic 0"** is input to the pin **"MODE1"**, WDT overflow reset will be masked.

5.4. Registers

Table 5-2 System State Register, Systate (SFR 0xA1)

Table 5-3 P0 IO Wakeup Flag Register (IOWKDET, SFR 0xAF)

When an event of reset Level 1 occurs, this register will be reset to its default state.

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Table 5-5 IO Wakeup Control Register (IOWK, SFR 0xC9)

Table 5-6 Set RTC Wake-Up Interval

Table 5-7 RTC Seconds Wake-up Interval Configuration Register (SECINT, SFR 0xDF)

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6.Clock

In V98XX, there are three clock generation circuits:

- **RC oscillator circuit:** To generate an RC clock (**"RCCLK"**). This circuit stops running only when the chip is powered off.
- **Crystal oscillator circuit:** To generate an OSC clock (**"OSCCLK"**). Generally, this circuit stops running only when the chip is powered off, but it also will stop running in some special circumstances. This circuit is monitored by the OSC monitoring circuit that is sourced by RC clock. When this crystal oscillator circuit stops running, the RC clock will replace the OSC clock to source all circuits that are sourced by the OSC clock, and the monitoring circuit will stimulate the crystal oscillator circuit until it runs again. When this crystal oscillator circuit stops running, the RC clock will replace the OSC dock to soul
all cricuits that are sourced by the OSC clock, and the monitoring circuit will stimulate the cryst
oscillator circuit unt
- **Phase-locked loop (PLL) circuit**: To generate a PLL clock (**"PLLCLK"**). The PLL locks onto a multiple of the **"OSCCLK"** frequency to provide a stable clock: **"PLLCLK"**. This circuit can be disabled.

The above three clocks can work as the clock sources for the functional units:

- Clock 1 (**"CLK1", "MCUCLK"**) provides clock pulses for MCU (Including CPU, RAM, Flash memory, interrupt circuits, timers/UART serial interfaces, GPSI, and IO ports). The OSC clock and PLL clock can be the optional source for **"CLK1"**. This clock is enabled by default, and it can be disabled.
- Clock 2 (**"CLK2", "MTCLK"**) provides clock pulses for the energy metering architecture. The OSC clock and PLL clock can be the optional source for **"CLK2"**. This clock is enabled by default, and it can be disabled.
- Clock 3 (**"CLK3", "LCDCLK"**) provides clock pulses for the LCD driver. The OSC clock is the source of this clock, and this clock is enabled by default, and it can be disabled only when PLL clock is selected as the source for **"CLK1"** and **"CLK2"**.
- Clock 4 (**"CLK4", "WDTCLK"**) provides clock pulses for WDT. The RC clock is the source of this clock. This clock is disabled and enabled together with **"CLK1"**.
- Clock 5 (**"CLK5", "RTCCLK"**) provides clock pulses for RTC. The OSC clock is the source of this clock. This clock cannot be disabled.

Figure 6-1 illustrates the clock system architecture of V98XX.

Figure 6-1 Clock System Architecture

6.1. RC Clock

In V98XX, there is an embedded RC oscillator circuit. It can generate an independent 32-kHz RC clock. It is the clock source for Clock 4 (**"CLK4"**) that provides clock pulses for WDT. The RC oscillator circuit will not stop running until the chip is powered off, but **"CLK4"** can be enabled or disabled together with **"CLK1"**.

There is a circuit monitoring the crystal oscillation and stimulating the oscillator to run again when it stops working. This circuit is sourced by the RC clock. When the crystal oscillator circuit stops running, the RC clock will immediately replace it to be the clock source for all circuits that are sourced by OSC clock. Users can read bit **"OSC"** (**"bit7"** of **"ANState"**, 0x286B) to detect whether the crystal stops running and has been replaced by RC clock to source all circuits.

6.2. OSC Clock

In V98XX, there is an embedded oscillator circuit with fixed capacitance of 12.5 pF. Connect this circuit to a 32768-Hz crystal around the pins **"CTO"** and **"CTI"** to compose a crystal oscillator circuit to generate a 32768-Hz OSC clock, an optional clock source for **"CLK1", "CLK2", "CLK3",** and **"CLK5"**. Users can configure the register **"P20FS"** (0x28C9) to measure the OSC clock waveform via pin **"P2.0"**. The clock frequency can be adjusted finely via configuring register **"CtrlCry1"** (0x2860) for the resistance and capacitance in the embedded oscillator circuit or connecting some additional capacitors around pins **"CTO"** and **"CTI"**. If RTC is used, bit **"XTRSEL<2:0>"** (**"bit[2:0]"** of **"CtrlCry1"**, 0x2860) must be set to

"0b011". It consumes 0.6 μA by default.

Generally, this circuit will not stop running until the chip is powered off, but some factors may cause the oscillator circuit to stop running. There is a circuit monitoring the crystal oscillation and stimulating it to run again when it stops working. This circuit is sourced by the RC clock. When the crystal oscillator circuit stops running, the RC clock will immediately replace it to be the clock source for all circuits that are sourced by OSC clock. Users can read bit **"OSC"** (**"bit7"** of **"ANState"**, 0x286B) to detect whether the crystal stops running and has been replaced with RC clock to source all circuits.

6.3. PLL Clock

The PLL circuit locks onto a multiple of the OSC clock frequency to provide some stable clock pulses, **"MEA_PLL"**, **"MCU_PLL",** and **"ADC_PLL",** for the energy metering architecture, MCU and its peripherals, and ADCs. **3. PLL CloCk**

Ne PLL circuit locks onto a multiple of the OSC clock frequency to provide some stable clock by

EA_PLL", "MCU_PLL", and "ADC_PLL", for the energy metering architecture, MCU and

hereins, and ADCs.

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Start MCU and then enable the PLL circuit. When the PLL circuit is disabled, it will output the 32768- Hz OSC clock.

Users can enable the PLL circuit, and select the PLL clock as the source for **"CLK1"** and **"CLK2"** by following the steps:

- 1. Access to the register **"CtrlCLK"** (0x2867) to enable the PLL circuit, and configure the frequency of **"MCUCLK"** and **"MTCLK"**;
- 2. Wait for the configuration till PLL has locked. MCU can access to the register **"PLLLCK"** (SFR 0xA3) and read the bit **"PLLLCK"** to detect the state of the PLL circuit.
- 3. When the PLL circuit has locked, set the bit **"MCUFRQ"** or **"MEAFRQ**" (**"bit0"** or **"bit7"** of **"SysCtrl",** SFR 0x80) to **'1'** to select the PLL clock as the source for **"CLK1"** or **"CLK2"**. This duration spends one PLL clock cycle only.

Users must follow the steps to reconfigure the **"MTCLK"** frequency or **"MCUCLK"** frequency when PLL circuit is enabled:

- 1. Access to the register **"SysCtrl"** (SFR 0x80) to select the OSC clock as the source for **"CLK1"** or **"CLK2"**;
- 2. Access to the register **"CtrlCLK"** (0x2867) to adjust the frequency of **"MTCLK"** or **"MCUCLK"**;
- 3. Access to the register **"SysCtrl"** (SFR 0x80) to select the PLL clock as the source for **"CLK1"** or **"CLK2".**

V98XX is 50/60Hz-power-line supportive. By default the chip is applied for 50Hz-power-line. Users can set the bit **"PLLSEL"** ("**bit5**" of **"CtrlPLL"**, 0x2868) to '1' to configure the chip for the application in 60- Hz power grid. The PLL clock frequency in 60-Hz power grid is 1.2 times of that in 50-Hz power grid. In 60-Hz power grid, the parameters related to the clock frequency, such as the baud rate and timers, must be reconfigured. If not specifically noted, all information related to the clock frequency in this datasheet will be applied to 50-Hz power grid only.

In the full-speed operation, the **"MCUCLK"** frequency is 13.1072 MHz, **"MTCLK"** frequency is 3.2768 MHz, and **"ADCCLK"** frequency is 819.2 kHz which is a quarter of **"MTCLK"** frequency. The typical load current in the full-speed operation is 5.5 mA.

6.4. Switching Source for CLK1 and CLK2

In V98XX, there are two methods to switch the source for **"CLK1"**, and only one method to switch the source for **"CLK2"**.

- **Normal operation.** In this mode, MCU needs to access some registers to select the clock source for **"CLK1"** or **"CLK2"**, and/or to disable/enable the clock;
- **Quick operation.** In this mode, only one register is needed by MCU to access to trigger the hardware to enable/disable the PLL circuit, select the source for **"CLK1"**, and/or enable/disable "**CLK1"**. If this method is used to disable **"CLK1"**, the system will enter **"Sleep"** state, but not **"Deep Sleep"** state. If the chip is used for a low-power application, this method will be recommended.

6.4.1. Normal Operation

6.4.1.1. Switch Source for CLK1 and Disable CLK1

When the RSTn pin reset, POR/BOR, or WDT overflow reset occurs, the analog control registers and the register **"SysCtrl"** (SFR 0x80) are reset to their default states, which means the PLL circuit is disabled and "CLK1" is enabled and sourced by the OSC clock. After reset, access the analog control registers to enable the PLL circuit and configure the frequency of **"MCUCLK"**, and then set the bit **"MCUFRQ"** (**"bit0"** of **"SysCtrl"**, SFR 0x80) to **'1'** to select the PLL clock as the source for **"CLK1"**. Only one OSC clock cycle is needed for all the above processes. this method is used to disable "CLK1", the system will enter "Sleep" state, but not "Deep Sitate. If the chip is used for a low-power application, this method will be recommended.

4.1. Normal Operation

4.1. Normal Operat

It is mandatory to enable the PLL circuit before writing **'1'** to the bit **"MCUFRQ"** to select the source for **"CLK1"**. When **"CLK1"** is sourced by the PLL clock, the PLL clock frequency will change to 32768 Hz automatically if the PLL circuit is disabled anomaly, but the bit **"MCUFRQ"** is still read out as **'1'.** In this condition, MCU must read the bit **"PLLLCK"** ("**bit0"** of **"PLLLCK",** SFR 0xA3) to detect the state of the PLL circuit.

When **"CLK1"** is sourced by the PLL clock, clear the bit **"MCUFRQ"** (**"bit0"** of **"SysCtrl"**, SFR 0x80) to select the OSC clock as the source for **"CLK1**". This switchover needs no more than one OSC clock cycle. In this period, the write operation on the analog control registers is invalid. MCU can keep on reading this bit immediately once it is cleared. If this bit is read out as **'0'**, it indicates the switchover is finished.

When **"CLK1"** is sourced by the OSC clock, and the bit **"PWRUP"** (**"bit0"** of **"Systate"**, SFR 0xA1) is read out as '0', write '1' to the bit "SLEEP0" or "SLEEP1" ("bit1" or "bit2" of "SysCtrl", SFR 0x80) to disable "CLK1" to force the system to enter "Deep Sleep" or "Sleep" state. When "CLK1" is disabled, MCU, including CPU, RAM, Flash memory, interrupt circuits, timers, UART interfaces, and GPIO ports, will stop working.

6.4.1.2. Switch Source for CLK2 and Disable CLK2

When the RSTn pin reset, POR/BOR, or WDT overflow reset occurs, the analog control registers and the register **"SysCtrl"** (SFR 0x80) will be reset to their default states, which means the PLL circuit is

disabled; **"CLK2"** is enabled and sourced by the OSC clock. After the reset, access to the analog control registers to enable the PLL circuit and configure the frequency of **"MTCLK",** and then set the bit **"MEAFRQ"** (**"bit7"** of **"SysCtrl"**, SFR 0x80) to **'1'** to select PLL clock as the source for **"CLK2"**. Only one OSC clock cycle is needed for all the above process.

It is mandatory to enable the PLL circuit and then to write **'1'** to the bit **"MEAFRQ"** to select the source for **"CLK2"**. When "**CLK2"** is sourced by the PLL clock, PLL clock frequency will change to 32768 Hz automatically if the PLL circuit is disabled anomaly, but the bit **"MEAFRQ"** is still read out as **'1'.** In this condition, MCU must read the bit **"PLLLCK"** (**"bit0"** of **"PLLLCK"**, SFR 0xA3) to detect the state of the PLL circuit.

When **"CLK2"** is sourced by PLL clock, clear the bit **"MEAFRQ"** (**"bit7"** of **"SysCtrl"**, SFR 0x80) to select the OSC clock as the source for **"CLK2"**. This switchover needs no more than one OSC clock cycle. In this period, the write operation on the analog control registers is invalid. MCU can keep on reading this bit immediately once it is cleared. When this bit is read out as '**0'**, it indicates the switchover is finished. hen "CLK2" is sourced by PLL clock, clear the bit "MEAFRQ" ("bit?" of "Systcht", SFR 0x81
et the OSC clock as the source for "CLK2". This switchover needs no more than one OSC clock
et in this perdal, the wire operation on

When **"CLK2"** is sourced by the OSC clock, write **'1'** to the bit **"PMG**" ("**bit4"** of **"SysCtrl"**, SFR 0x80) to disable **"CLK2"**. When **"CLK2"** is disabled, the energy metering architecture will stop working.

6.4.2. Quick Operation

This mode is applied to disable/enable the PLL circuit, select the source for **"CLK1"** and enable/disable **"CLK1"**. In this mode, only the register **"SysCtrl"** (SFR 0x80) needs to be accessed.

When the RSTn pin reset, POR/BOR, WDT overflow reset, power recovery event, or IO/RTC wakeup event occurs, the bits **"FWC"** and **"FSC" ("bit6"** and **"bit5"** of **"SysCtrl"**, SFR 0x80) are reset to 0s. So the program determines the state of the system, including the PLL circuit and the clock source for **"CLK1"**.

Clear the bit **"FSC"**, and then write **'1'** to the bit **"FWC"**, to enable the PLL circuit and select the PLL clock as the source for **"CLK1"** automatically. In this condition, the PLL clock frequency is 3.2768 MHz. The source for **"CLK1"** will be switched to PLL clock immediately once **'1'** is written to the bit **"FWC"**.

When the bit **"PWRUP"** (**"bit0"** of **"Systate"**, SFR 0xA1) is read out as **'0'**, write **'1'** to the bit "**FSC"** whatever the bit **"FWC"** is, to select the OSC clock to be the source for **"CLK1"**, to disable the PLL circuit, to disable **"CLK1"**, and to force the system to enter the **"Sleep"** state.

6.4.3. Normal Operation vs. Quick Operation

When the RSTn pin reset, POR/BOR, WDT overflow reset, power recovery event, or IO/RTC wakeup event occurs, the system will get into a temporary state in which the OSC clock is used as the clock source for **"CLK1"** and the energy accumulation unit can accumulate a constant only. In this state, the system consumes some power that should be diminished for the low-power-consumption applications. In the power-down state, the process of disabling the circuits consumes some power that should be also diminished.

In the normal operation, applications need to access analog control registers to get the system out of the temporary state or to disable the circuits in the power-down state. But in the quick operation, only

the bits **"FSC"/"FWC"** need to be accessed. So, completing the above implementations in the quick operation is preferred.

But, as stated above, the clock source switchover in the normal operation and quick operation may affect each other:

- If the bits **"FSC"/"FWC"** are set to **"0b01"**, the configuration of the register **"CtrlCLK"** (0x2867) and the bit **"MCUFRQ"** (**"bit0"** of **"SysCtrl"**, SFR 0x80) cannot be activated, and the PLL clock frequency holds 3.2768 MHz.
- If the bit **"MCUFRQ"** is read out as **'1',** clearing the bits **"FSC"/"FWC"** cannot switch the clock source for **"CLK1"**.

To prevent MCU from the mis-operation, MCU can combine both methods, the combination operation: To enable the PLL circuit and switch the source for **"CLK1"** in the quick operation to lower the power consumption; and then, to hold the PLL clock frequency in the normal operation.

```
FWC = 1; // Turn on PLL, and switch the clock source to PLL clock
MCUFRQ = 1; // when PLL clock is the source for Clock 1
```
In the following table, the normal, quick, and combination operations are compared.

Table 6-1 Comparing Normal, Quick, and Combination Operation

The arrow in the following figure indicates the process from the IO wake-up event to completing the clock source switchover of **"CLK1"** to the 3.2768-MHz PLL clock, in the quick operation or combination operation, which lasts 800 μs \sim 900 μs, including the time to reset, to execute the initial long jump instruction, and to write '1' into "FWC".

Figure 6-2 Enabling PLL Circuit and Clock Source Switchover to PLL in Quick Operation

The arrows in the following figure indicate the process from the clock source switchover of **"CLK1"** to **"OSC"** clock to disabling **"CLK1"**, in the quick or combination operation, which lasts less than 30 μs.

6.5. Registers

Table 6-2 Clock Switchover Control Register (SysCtrl, SFR 0x80)

system from the sleeping state but cannot reset the system. After wakeup, CPU keeps on executing programs; all circuits hold their states where they were before sleeping; only **"bit[2:1]"** (**"SLEEP1"** and **"SLEEP0"**) and **"bit[6:5]"** (**"FWC"** and **"FSC"**) are cleared.

Table 6-3 Peripheral Control Register 0 (PRCtrl0, 0x2D00)

Table 6-5 Register 1 to Adjust OSC Clock Frequency

Table 6-6 Register 2 to Adjust OSC Clock Frequency

Table 6-7 PLL Clock State Register (PLLLCK, SFR 0xA3)

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Table 6-8 Register 1 to Adjust Clock Frequency of Specific Functional Blocks

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Table 6-9 Register 2 to Adjust Clock Frequency of Specific Functional Blocks

Table 6-10 OSC Clock State Register

7.Power Management

V98XX has three system states according to the state of Clock 1:

- **OSC state:** When a reset event of Level 1 or Level 2 occurs, the system will go to the OSC state, in which Clock 1 runs and is sourced by the OSC clock.
- **Working state:** The PLL circuit is enabled, and the PLL clock is used as the source for Clock 1.
- **Sleeping state:** When the bit **"PWRUP"** (**"bit0"** of **"Systate"**, SFR 0xA1) is cleared, select the OSC clock as the source for Clock 1 and disable Clock 1, and then the system will enter the sleeping state. By default, the chip will be woken up with reset and be forced to go back to the OSC state. But when the bit **"IORSTN"** (**"bit0"** of **"IOWK"**, SFR 0xC9) is set to **'1',** the chip will be woken up without reset, which means the chip is woken up and goes back where it entered the sleeping state except that bits "SLEEP1", "SLEEP0", "FWC", and "FSC" ("bits" of "SysCtrl", SFR 0x80) are cleared to 0s. The sleeping state is classified to 2 states: **"Sleep"** and **"Deep Sleep"**. An IO/RTC wakeup event, CF pulse output, or a power recovery event can wake up the system from **"Sleep"**. An IO wakeup event or a power recovery event can wake up the system from **"Deep Sleep"**.

7.1. Power Consumption

shown in Table 7-1.	7.1. Power Consumption			OSC clock as the source for Clock 1 and disable Clock 1, and then the system will enter the sleeping state. By default, the chip will be woken up with reset and be forced to go back to the OSC state. But when the bit "IORSTN" ("bit0" of "IOWK", SFR 0xC9) is set to '1', the chip will be woken up without reset, which means the chip is woken up and goes back where it entered the sleeping state except that bits "SLEEP1", "SLEEP0", "FWC", and "FSC" ("bits" of "SysCtrl", SFR 0x80) are cleared to 0s. The sleeping state is classified to 2 states: "Sleep" and "Deep Sleep". An IO/RTC wakeup event, CF pulse output, or a power recovery event can wake up the system from "Sleep". An IO wakeup event or a power recovery event can wake up the system from "Deep Sleep". In V98XX, there are a lot of functional units, some of which can be disabled, but others cannot. The power consumption of these units may be affected by the digital power supply or the clock frequency as	
		Stoppable?	Table 7-1 Factors Affecting Power Consumption of Each Unit Factors Affecting Power Consumption.		
Unit	State When Powered On		Clock Frequency	Operation Voltage (DVCC Output)	
LD033	On	No	No	No	
Digital Power Supply Circuit	On	No	No	No	
OSC	On	No	No	No	
MCU	On	Yes	Yes	Yes	
REF_LP	On	No	No	No	
RTC	On	No	No	No	
PLL	Off	Yes	No	No	
BandGap	Off	Yes	No	No	

Table 7-1 Factors Affecting Power Consumption of Each Unit

7.1.1. OSC State

When a reset event of Level 1 or Level 2 occurs, the system will be reset to the OSC state. In this state, LDO33 is enabled, OSC clock is used as the source for **"CLK1"**, and MCU runs.

Table 7-2 OSC State of System

7.1.2. Working State

In the OSC state, enable the PLL circuit, select the PLL clock to work as the source for "CLK1", and then the system will enter the working state.						
In the working state, users can configure the MCU clock ("CLK1") frequency, and enable the required ADCs, the energy metering architecture, the LCD driver, and CPU and its peripherals according to the application.						
In the working state, when the frequency of "CLK1" is set to 13.1072 MHz, that of "CLK2" is set to 3276.8 kHz, and sampling frequency of ADCs ("ADCCLK") is set to 819.2 kHz, the system will run at full speed. When the system works normally, the power consumption of the global system will be determined by the number of enabled ADCs, and the configuration of the metering architecture and the LCD driver.						
State When Powered on	Stoppable?	Current State				
On	No	On				
On	No	On				
On	No	On				
On.	No	On				
On.	No	On				
Off	Yes	On				
Off	Yes	On				
On	No	On				
Off	Yes	Off				
Off	Yes	Off				
		Table 7-3 Power Consumption When System Working at Full Speed				

Table 7-3 Power Consumption When System Working at Full Speed

7.1.3. Sleeping State

When the bit **"PWRUP"** (**"bit0"** of **"Systate"**, SFR 0xA1) is read out as **'0'**, switch the source for **"CLK1"** to the OSC clock and then disable **"CLK1"**, then the system will go to the sleeping state.

There are two types of sleeping state: **"Sleep"** and **"Deep Sleep"**.

In **"Sleep"** or **"Deep Sleep"**, RTC holds on; the memories, CPU and its peripherals stop working; but the LCD driver and the energy metering architecture will not stop working until they are disabled. If ADCs, PLL circuit, LCD driver, and energy metering architecture are disabled, and IOs are set to **"output, disabled; input, masked"** before entering **"Sleep"** or **"Deep Sleep"**, the system consumes the lowest power.

In **"Sleep"**, if IO/RTC wakeup event, CF pulse output, or power recovery event occurs, the system will be woken up and go back to the OSC state by default. In **"Deep Sleep"**, only an IO wakeup event or power recovery event can wake up the system and reset it to the OSC state by default. When the bit **"IORSTN"** (**"bit0"** of **"IOWK"**, SFR 0xC9) is set to **'1'**, any wakeup event can wake up the system from **"Sleep"** or **"Deep Sleep"** only but cannot reset the system to the OSC state. In this condition, the chip will go back where it entered the sleeping state, except that **"bit[6:5]"** (**"FWC"** and **"FSC"**) and **"bit[2:1]"** (**"SLEEP1"** and **"SLEEP0"**) will be cleared to 0s. and CLK3 is running.

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S.5.5 mA

Wanter Consumption

S.5.5 mA

Natally the term of the bit "PWRUP" ("bit0" of "Systate", SFR 0xA1) is read out as '0", switch the source

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If the pin **"WAKEUP1", "WAKEUP2", "WAKEUP3",** or **"WAKEUP4"** is set to **"Input enabled"** before the system enters **"Sleep"** or **"Deep Sleep"**, a transition (Either high-to-low or low-to-high, with more than 4 OSC clock cycles on both levels) on the pin in **"Sleep"** or **"Deep Sleep"** can wake up the system. By default ports **"P0.2"** and **"P0.3"** are not used for the wakeup event input. Users must configure bit **"IOP0"** ("**bit1**" of **"IOWK"**, SFR 0xC9) to **'1'** to set both pins for the wakeup input. When the bit "IO" ("bit3" of "Systate", SFR 0xA1) is set to '1', read states of bits "P14WK" ("bit0" of "**IOWKDET"**, SFR 0xAF), **"P02WK"** (**"bit1"** of **"IOWKDET"**, SFR 0xAF) and **"P03WK"** (**"bit2**" of **"IOWKDET"**, SFR 0xAF) to detect which IO wakeup event woke up the chip from the sleeping state.

If both bit **"RTC"** (**"bit2"** of **"Systate"**, SFR A1) and **"CFWK**" (**"bit3"** of **"IOWKDET"**, SFR 0xAF) are set to 1s, it indicates that the system was woken up by the CF pulse output. If the bit **"RTC"** is set to **'1',** but **"CFWK"** is cleared, it indicates that an RTC wakeup event occurred.

7.1.3.1. Sleep/Wake-Up

In V98XX, there are two methods to wake up the system from the sleeping state or make the system go to the sleeping state: Normal method and quick method.

1. Normal Method

The normal method for wakeup/sleep switchover is totally controlled by the program.

When the PLL clock is enabled and works as the source for the MCU clock (**"CLK1"**), users can follow steps illustrated in Figure 7-1 to force both MCU and energy metering architecture to go to the sleeping state, or force MCU to go to the sleeping state only but leave the energy metering architecture to accumulate a constant for the energy metering. is illustrated in Figure 7-1 to force both MCU and energy metering architecture to go to the sleeping state only but leave the energy metering architecture for the sleeping state only but leave the energy metering architec

Figure 7-1 Go to Sleeping State (Normal Method, Disable PLL Clock)

When the PLL clock is enabled and works as the source for the MCU clock (**"CLK1"**), users can follow

steps illustrated in [Figure 7-2](#page-93-0) to force MCU to go to the sleeping state only but leave the energy metering architecture work normally.

Figure 7-2 Go to Sleeping State (Normal Method, PLL Clock Holds on)

In **"Sleep"** or **"Deep Sleep"**, when IO/RTC wakeup event, CF pulse output, or power recovery event occurs, the system will be woken up from the sleeping state. If the wakeup with reset mode is applied, after a reset, users should use the normal operation to enable the PLL circuit and select it as the source for **"CLK1"** to make the system go to the working state.

2. Quick Method

In V98XX, the quick method can force the system to go to **"Sleep"**, but not **"Deep Sleep"**.

When the PLL clock is enabled and works as the source for the MCU clock (**"CLK1"**), users can follow steps illustrated in [Figure 7-3](#page-94-0) to force both MCU and energy metering architecture to go to **"Sleep"**, or force MCU to go to **"Sleep"** only but leave the energy metering architecture to accumulate a constant for energy metering. In this case, PLL clock will be disabled definitely.

Figure 7-3 Go to Sleep (Quick Method)

In "Sleep", IO/RTC wakeup event, CF pulse output, or power recovery event can wake up the system. If the wakeup with reset mode is applied, users should use the quick operation to enable the PLL circuit and switch the source for "CLK1" to make the system go to the working state.

7.1.3.2. Power Consumption in Sleeping State

The following table shows the power consumption in the sleeping state when the LCD driver is disabled.

Table 7-5 Power Consumption in Sleeping State

7.2. Registers

Table 7-6 Register for Clock Control

(**"SLEEP1"** and **"SLEEP0"**) and **"bit[6:5]"** (**"FWC"** and **"FSC"**) are cleared.

Table 7-7 Register to Indicate Power Supply State

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8.Power Supply

V98XX supports 5-V or 3.3-V power input on the pin **"VDD5"**. The power supply is supervised continuously. The internal analog circuits and general-purpose I/O (GPIO) ports are powered by the 3.3V regulator circuit (3.3V-LDO), and the peripheral circuits are powered by the LDO33 output voltage; the Vango metering architecture and PLL circuit are powered by the digital power supply circuit.

There is an internal power detection circuit in V98XX. By default this circuit is enabled. When the chip is 3.3 V powered, users must set bit **"PDDET"** (**"bit7"** of **"CtrlLDO",** 0x2866) to **'1'** to disable this circuit to protect the battery from the current leakage when a battery is connected. When the chip is 5 V powered, this bit must hold its default value.

Figure 8-1 Power Supply Architecture

Note:

V98XX has an internal power supply detection circuit. The circuit is turned on by default. When the system is powered by a 3.3-V power source, users must set **"PDDET**" (**"bit7", "CtrlLDO",** 0x2866) to **'1'** to disable the power detection circuit, or when a battery is connected, the battery leakage may occur. The bit must be cleared when it is powered by 5-V power supply. By this way the battery leakage risk will not exist.

8.1. 3.3-V Regulator Circuit (LDO33)

In V98XX, the analog circuits and the GPIO ports are powered by the 3.3-V regulator circuit (**"LDO33"**), and the peripheral circuits are powered by the LDO33 output voltage. This LDO33 will not stop working until the chip is powered off. The LDO33 output voltage can be configurable via bits **"LDO3SEL"** (**"bit[5:3]"** of **"CtrlLDO"**, 0x2866).

This LDO33 has a driving capability of 30 mA. When the load current through the analog circuits and

the GPIO ports is less than 30 mA, the LDO33 output voltage holds 3.3 V; when the load current is higher than 30 mA, the higher the load current is, the lower voltage the LDO33 will output.

It is recommended to decouple the pin "**LDO33"** externally with $a \geq 4.7$ µF capacitor in parallel with a 0.1-μF capacitor.

Figure 8-2 LDO33 Output and 5V Power Input

8.2. Digital Power Supply

In V98XX, the PLL clock generation circuit and the Vango metering architecture (VMA) are powered by the digital power supply circuit. When the digital power supply output is 200 mA, being lower than the power input on the pin **"VDD5"**, it will output a stable voltage, avoiding the digital power fluctuation caused by the variation of the power input. The digital power supply output is configurable via the bit **"LDOV2SEL"** (**"bit[2:0]"** of **"CtrlLDO"**, 0x2866). Figure 8-2 LDO33 Output and 5V Power

Trigune 8-3 LDO33 Output and the Load

Input

Trigune 8-3 LDO33 Ou

The digital power supply circuit has a driving capability of 35 mA. When the load current through the circuits is less than 35 mA, the digital power supply will be stable; when the load current is higher than 35 mA, the higher the load current is, the lower the digital power supply will be.

This power supply circuit will not stop working until the system is powered off.

It is recommended to decouple the pin **"DVCC"** externally with a ≥4.7 μF capacitor in parallel with a 0.1-μF capacitor.

8.3. Power Supply Supervisor

In V98XX, the 5-V main power is input into the pin **"VDCIN"** after a resistive divider. The input voltage on the pin **"VDCIN"** is monitored continuously by the power supply supervisor.

When the input voltage on the pin **"VDCIN"** is lower than 1 V, a power-down event will occur, the bit **"PWRDN"** (**"bit1"** of **"Systate"**, SFR 0xA1) will be set to **'1',** and a power-down interrupt will be generated to CPU.

Figure 8-4 Relationship between VDCIN Input Signal and States of Flag Bits PWRUP and PWRDN

8.4. Battery Supply

V98XX can be powered by batteries. Users can read the value of the flag bit **"PWRUP"** (**"bit0"** of **"Systate"**, SFR 0xA1) to get the state of the power supply. When this bit is read out as **'0'**, it indicates the input voltage on the pin **"VDCIN"** is lower than 1.0 V, which means the system is powered by the battery, or the power supply has been switched from 5-V power to the battery.

When the chip is powered by batteries, please note that the battery will get passive when it is reactive for a long time. So users should set the bit **"BATDISC**" (**"bit0"** of **"CtrlBAT"**, 0x285C) to **'1'** at an interval to discharge the battery to protect them from passivation. During the battery discharge, the load current is 3 mA, and the period for battery discharge should not be too long to save power. After discharge, the bit **"BATDISC"** must be cleared.

9.Comparator

Figure 9-1 Comparator Architecture

- Positive signal input on pin **"M1"** and negative signal input on pin **"M2"**;
- Positive signal input on pin **"M1"** and negative signal from internal low power reference circuit (REF_LP);
- Positive signal input on pin **"M2"** and negative signal from internal low power reference circuit (REF_LP).

					1.2V REF_LP			
					Figure 9-1 Comparator Architecture			
					V98XX integrates one additional comparator CB to compare the analog signals:			
\bullet	Positive signal input on pin "M1" and negative signal input on pin "M2";							
\bullet	Positive signal input on pin "M1" and negative signal from internal low power reference circuit (REF_LP) ;							
\bullet	Positive signal input on pin "M2" and negative signal from internal low power reference circuit (REF_LP) .							
When the RSTn pin reset, POR/BOR, or WDT overflow reset occurs, or the system is in "Sleep" or "Deep Sleep" state, this comparator will stop running.								
			"Ox286B") to detect the comparison result of the input signals. Table 9-1 Registers Related to Comparator CB		When IE6=1 ("bit6" of "0x28A5"), EIE.3=1 ("bit3" of "SFR 0xE8"), and IE.7=1 ("bit7" of "SFR OxA8") , the comparator interrupt will be enabled. In this state, the interrupt flag "IR6" ("bit6" of "Ox28A2") will be set to '1' when the output of the comparator changes, and the comparator will generate an interrupt to CPU. After the interrupt service, users can read bit "COMPB" ("bit5" of			
	Register	Bit		Default	Description			
		Bit4	CMPIT	0	To select the bias current input to the comparator CB 0: 20 nA; 1:200 nA.			
	0x2861				To select the analog input to the comparator CB			
	CtrlCry2				00: M2 for positive input; REF_LP for negative input;			
	bit[3:2]	CMPSSELB<1:0>	0	01: M1 for positive input; REF_LP for negative input;				
					10/11: M2 for positive input; M1 for negative input.			

Table 9-1 Registers Related to Comparator CB

10. Energy Metering

The energy metering architecture in V98XX has features:

- Four independent oversampling Σ/Δ ADCs: One voltage channel (U), two current channels (I), and one multifunctional channel for various signal measurements.
- High metering accuracy:
	- Less than 0.1% error on active energy metering over dynamic range of 5000:1.
	- Less than 0.1% error on reactive energy metering over dynamic range of 3000:1.
	- Less than 0.5% error on current and voltage RMS calculation over dynamic range of 1000:1. Less than 0.1% error on reactive energy metering over dynamic range of 3000:1,

	Less than 0.5% error on current and voltage RMS calculation over dynamic range of 1000:

	Providing measurements:

	Raw waveform and DC componen
- Providing measurements:
	- Raw waveform and DC component of current/voltage signals
	- Instantaneous/Average and active/reactive power
	- Positive/Negative and active/reactive energy
	- Average apparent power
	- Instantaneous/average current/voltage RMS
	- Line frequency
	- Temperature with measurement accuracy of $\pm 1^{\circ}$ C
	- Battery voltage, system voltage, and external voltage signals
- Two current inputs for active energy, or one current input for active and reactive energy
- Programmable energy metering modes:
	- Accumulating power, current RMS, or a constant for energy metering
	- Accumulating energy at a configurable frequency
- Current detection, to lower power consumption
- CF pulse output and interrupt with configurable pulse width
- Zero-crossing interrupt
- Programmable threshold for no-load detection
- Calibrating meters via software:
	- Phase compensation supported, resolution $0.005^{\circ}/$ lsb (min.), over a range of $\pm 1.4^{\circ}$ (min.)
	- Gain calibration of RMS and power, and offset calibration of power
	- Accelerating meter calibration when low current is applied.

Figure 10-1 Digital Signal Processing in Vango Metering Architecture

10.1. Accessing to Registers for Vango Metering Architecture

In V98XX, MCU must write or read of the metering control, data and calibration registers through the buffer registers.

1. Buffer registers for write and read operation.

When a POR/BOR, RSTn pin reset, or WDT overflow reset event occurs, all buffer registers for the write and read operation on the registers for energy metering architecture will be reset to their default states.

Data	ACK	INVD	DATA[31:24]	DATA[23:16]	DATA[15:8]	\vert DATA[7:0]
Buffer Register	BUFF5	BUFF4	BUFF3	BUFF ₂	BUFF1	BUFFO
Address	0x2885	0x2884	0x2883	0x2882	0x2881	0x2880

Table 10-1 Buffer Registers and Data to Be Written or Read

2. Read operation

MCU must read the registers for energy metering architecture following steps as illustrated:

- a. Write **"0xCC"**, and then **"0s"** to the register **"INVD"** located at address **"0x2884"**;
- b. Read the address of the target register;
- c. When the flag bit **"ACK"** is read out as **'0'**, or in no more than 24 MTCLK clock periods, the content (DATA) of the target register will be loaded into the buffer registers in sequence as illustrated in the preceded table;
- d. Read the buffer registers to acquire the content (DATA).

3. Write operation

MCU must write of the registers for energy metering architecture following steps as illustrated:

- a. Write **"0xCC"**, and then **"0s"** to the register **"INVD"** located at address **"0x2884"**;
- b. Write the data (DATA) to the buffer registers in sequence as illustrated in the preceded table;
- c. Write of the address of the target register;
- d. When the flag bit **"ACK"** is read out as **'0'**, or in no more than 24 MTCLK clock periods, the content (DATA) in the buffer registers will be loaded into the target registers.

10.2. Metering Clock

"CLK2" provides clock pulse for the energy metering architecture, including ADCs. It is sourced by OSC clock or PLL clock. When **"CLK2"** is disabled, the metering architecture stops running.

There is a specific bit (**"GT"**, **"bit7"** of **"IDET"**, 0x2886) to gate control the clock for the sampling circuits and RMS/power calculation circuits. When this bit is set to '1', the circuits stop working, but the energy accumulation unit keeps on running.

In working state, the PLL clock is enabled, and it is selected as the source for **"CLK2"**. In this condition, the metering clock frequency (f_{MTCLK}) and sampling frequency of ADCs (f_{ADC}) are configurable, and f_{MTCLK} must be 4 times of f_{ADC} .

Table 10-2 Configuration of CLK2

10.3. Reference Voltage

In the V98XX, the BandGap circuit outputs a reference voltage (about 1.185V with a typical temperature drift of 10ppm/°C) and bias current for ADCs and PLL circuit. So users must enable the

BandGap circuit before enabling ADCs or PLL circuit.

Users can improve the BandGap performance via adjusting the temperature coefficient as follows:

- 1. Set bit BGPPDN (bit6 of CtrlCLK, 0x2867) to 1 to enable the BandGap circuit;
- 2. Ensure that the bit BGPCHOPN (bit0 of CtrlBGP, 0x2862) is cleared, which enables the chopper to remove the DC component of the BandGap circuit. When the chopper is enabled, the output voltage of the BandGap circuit varies over the range $-50 \sim +50$ mV, and the temperature coefficient is improved.
- 3. Configure bits REST<2:0> and RESTL<1:0> (bit[5:1] of CtrlBGP, 0x2862) to adjust the temperature coefficient to eliminate the temperature coefficient introduced by external components. A temperature coefficient drift of x in the BandGap circuit results in a drift of -2x in the meter measurement error.

Figure 10-2 The temperature characteristic curve of reference voltage

In the V98XX, a circuit is designed to supervise the current leakage of the external decoupled capacitors connected to the pin REF. When bit REFLKEN (bit7 of CtrlCry2, 0x2861) is set to 1, an interrupt, REF leakage interrupt, will be triggered when the reference voltage is lowered by 3% caused by current leakage, and flag bit IR4 (bit4 of ExInt4IFG, 0x2850) is set to 1. When IE4=1 (bit4 of ExInt4IE, 0x2853), EIE.2=1 (bit2 of SFR 0xE8) and IE.7=1 (bit7 of SFR 0xA8), this circuit will generate an interrupt to CPU when flag bit IR4 is set to 1.

10.4. Analog Inputs

The V98XX has three pairs of analog inputs forming two current channels and one voltage channel. The current channels consist of two fully differential voltage inputs. And the voltage channel consists of

a pseudo differential voltage input: UP is positive input for the voltage channel, and UN, grounded, is negative input for the voltage channel. Each input has a maximum voltage of ±200mV, and each pair has a maximum differential voltage of ±400mV.

In a current channel, a current transformer (CT) or a shunt resistor can be used for analog inputs.

Figure 10-4 Shunt Resistor Network for Current Analog Input

In the voltage channel, a potential transformer (PT) or a resistor-divider network can be used for analog inputs.

Figure 10-5 Analog Input of Voltage

The full measurement scale of ADCs is ± 1.1 V. To match the output signal of the sensors with the measurement scale of ADCs, groups of Analog Programmable Gain Amplifiers (APGA) are set. The product of the analog input and the set APGA should not be over ±1.1 V.

10.5. Analog-to-Digital Conversion

Second-order Σ-ΔADCs are designed in three channels of V98XX for analog-to-digital conversion, and their full measurement scale is ±1.1 V. By default, Σ-ΔADCs are disabled. Users can enable them via configuring **"CtrlADC6"** register (0x2864).

Note: It is mandatory to clear bit **"DCENN"** (**"bit7"** of **"CtrlLCDV"**, 0x285E) to add 10-mV direct voltage offset to the current input to current channel ADCs.

After analog-to-digital conversion, the analog signals are converted to be 1-bit code streams of 22-bit length with both **"bit21"** and **"bit20"** being the sign bits.

Table 10-4 Enable/Disable ADCs

10.6. Switch of Current Channels

After analog-to-digital conversion, current IA or IB is sent to Current I1 or Channel I2, via configuring the bit **"SELI"** (**"bit5"** of **"PMCtrl1"**, 0x0100), for different signal processing.

Figure 10-6 Exchange of Current Channels

Table 10-5 Control Bit for Switching Current Signals

Then current (I1 and I2) and voltage signals must be input to a phase compensation circuit to correct the phase angle error between the current and voltage signals introduced by the transformers.

10.7. Phase Compensation

A phase compensation circuit composed of a time delay chain of fixed length is applied to correct the phase angle error via delaying the selected signal. Either current or voltage signals can be delayed.

By default phase compensation is disabled. Users can enable this function via configuring the bit **"PHCEN"** (**"bit6"** of **"PMCtrl1"**, 0x2878). When phase compensation is enabled, the phase angle error between I1 and U, and I2 and U, are corrected respectively. **"Bit [7:0]"** of register **"PHCCtrl1"** (0x287B) together with **"bit[1:0]"** (IAPHC) of register **"CRPST"** (0x287F) or **"bit[7:0]"** of register **"PHCCtrl2"** (0x287C) together with **"bit[3:2]"** (IBPHC) of register **"CRPST"** (0x287F) are used to calibrate the phase angle error between signal I1 or I2 and the voltage signal, see Table 10-7 for details.

In 50-Hz power grid, when the sampling frequency of the phase compensation circuit (*fsmpl*) is 3.2768 MHz, the calibration resolution is 0.0055°/lsb, and the maximum phase angle error to be corrected is 1.4°. The value of *fsmpl* is determined by the configuration of bits **"MEACLKSEL<1:0>"** (**"bit[3:2]"** of **"CtrlCLK"**, 0x2867).

At a lower power factor (PF), the phase angle error can cause greater energy metering error. So generally, the phase angle error is calibrated at PF=0.5L to ensure the metering accuracy. When PF=0.5L, users can use a simple equation as follows to calculate the value N.

$$
N = Round\left(\frac{3011}{2} \times E \times \frac{f_{smpl}}{819200}\right)
$$
 Equation 10-1where,

N is the value, signed, to be set to the phase compensation control registers to correct the phase angle error. A positive N indicates that current signal must be delayed, so "0" must be set to the sign bit; a negative N indicates that the voltage signal must be delayed, so "1" must be set to the sign bit;

E is the energy metering error displayed in LCD screen of the calibration equipment;

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fsmpl is the sampling frequency of the phase compensation circuit, Hz.

Table 10-6 *fsmpl* **Determines Phase Compensation Resolution and Correction Range**

Table 10-7 Registers for Phase Compensation

x=A or B. **"PHCx7"** is the sign bit, **"PHCx6"** is not used, and the other 8 bits are used to set the absolute value to correct the phase angle error.

10.8. Digital Input

In V98XX, decimation filters are designed to reduce the noise of the 1-bit code stream output from the oversampling Σ/ΔADC and to reduce the sampling frequency to 1/256 of *fADC*.

Figure 10-8 Digital Inputs

"Bit[2:0]" of the register **"PMCtrl1"** (0x2878) enables or disables the code stream input into the decimation filter. When this function is enabled, the code stream will be input to the filter; otherwise, 0s are input for digital signal processing.

Table 10-8 Enable/Disable Digital Inputs

As depicted in the above figure, the signal output from the decimation filter in each channel will be sent to a high-pass filter (HPF) to remove the DC components introduced by the sensors and ADCs. In the V98XX, this high-pass filter cannot be disabled. When the **"ADCCLK"** frequency is 819.2 kHz, this filter will be settled in 60 ms in 50-Hz power grid, and in 50 ms in 60-Hz power grid.

Digital programmable gain amplifiers (DPGA) with possible gain selection via **"PMCtrl2"** (0x2879) and **"PMCtrl3"** (0x287A) are applied to digital signals output from the high-pass filters to amplify their capability of depressing truncation noise when a low signal was input. Please note the product of the analog input and the total PGA gains, including APGA and DPGA, should not be over the measurement scales of the ADCs.

The following equations describe the digital signals processed by the digital programmable gain amplifiers:

> Ia = PGAdia × PGAia × $\frac{\text{Aia}}{1.185}$ × sin(ωt + ψ) = DIa × sin(ωt + ψ) Ua = PGAdua × PGAua × $\frac{\mathsf{A} \mathsf{u} \mathsf{a}}{1.185}$ × sin ωt = DUa × sin ωt Equation 10-2

where, *PGAdua* and *PGAdia* are the DPGA gains; *PGAua* and *PGAia* are the APGA gains; *Aua* and *Aia* are the amplitude of current and voltage inputs; and 1.185 is the reference voltage.

10.9. Current Detection

To lower power consumption, a current detection circuit is designed in the V98XX to compare the AC component of the instantaneous I1 current signal with the preset threshold in register IDETTH (0x1002). Set bit DETON (bit4 of IDET, 0x2886) to 1 to enable current detection, and configure bit[3:0] of IDET (0x2886) for current detection window width ([IDLEN]+1). When ([IDLEN]+1) continuous current samples are detected to be higher than the preset threshold, it is defined a current signal is caught, and flag bit CST (bit6 of IDET, 0x2886) is set to 1. Users must set bit CLR (bit5 of IDET, 0x2886) to 1 or clear bit DETON to clear bit CST. BitL2:01

For U signal is lowered to 1/4 of its configuration. When bit LPH

re following equations describe the digital PGA gain for U signal is what it is configured.

Mifflers:

Un-F6Adava XFAdava X Auso X and = Dilax

The configuration of bit IDLEN (bit[3:0] of IDET, 0x2886) and the current detection period have a relationship as follows:

> $t_{IDT} =$ $256 \times ([IDLEN] + 1)$ fadc Equation 10-3

where, 256 means the decimation filter (CIC) has reduced the sampling frequency to 1/256 of *fADC*, the sampling frequency of the oversampling ADC; [IDLEN] is the configuration of bits IDLEN; *tIDT* is the current detection period, in unit of ms. To perform current detection, it is mandatory to enable the metering clock (MTCLK), and enable power/RMS calculation.

10.10. RMS Calculation and Calibration

The V98XX supports RMS calculation. By default this function is disabled. When RMS calculation is enabled, users can enable the band-pass filter in the RMS calculation circuit via bit BPFEN (bit6 of PMCtrl3,

0x287A) and configure the filter coefficient via register PARABPF (0x10EF) to improve calculation accuracy.

As illustrated in Figure 10-9, the current or voltage signal output from the high-pass filter is multiplied with itself in the multiplier to get the product with the second harmonic which can be removed by the low-pass filter, and then the signal processed output from the low-pass filter is sent to the circuit for rooting processing that produces a 32-bit datum, the raw RMS value of current or voltage. The raw RMS data will be gain calibrated and then stored in instantaneous RMS registers. Besides, the instantaneous RMS data will be averaged to acquire the average RMS data that are stored in average RMS registers.

If the raw RMS value is represented as RMS', the gain calibration value is represented as S, and the instantaneous RMS is represented as RMS, then the above three values have the relationship:

RMS=RMS'×(1+S) Equation 10-4

Figure 10-9 RMS Calculation and Calibration

The content of all the instantaneous and average RMS data registers are in the form of 32-bit 2' complement. When POR/BOR, RSTn pin reset or WDT overflow reset occurs, these registers are reset to their default states.

10.11. Apparent Power Calculation

The V98XX supports apparent power calculation. This function is enabled or disabled together with RMS calculation.

In the V98XX, the average current and voltage RMS are multiplied to acquire the apparent power, as described in the following equation:

where, *S* represents apparent power; *Irms* and *Urms* are the average current and voltage RMS.

The content of the apparent power registers are in the form of 32-bit 2'-complement. When POR/BOR, RSTn pin reset or WDT overflow reset occurs, these registers are reset to their default states.

10.12. Power Calculation and Calibration

The V98XX supports active/reactive power calculation. This function is enabled or disabled together with the RMS calculation and apparent power calculation.

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 126 CO
 Hangzhou Vango Texhove Technologies, are in the form of 32-bit 2:
 HDOWER Calculation
 126 CO
 126 There are two paths for power calculation, energy accumulation and energy pulse generation: E1 path and E2 path. E1 path is used for active power calculation and energy accumulation only; but, E2 path can be configured for active or reactive power calculation and energy accumulation which is determined by bit DBLEN (bit4 of PMCtrl3, 0x287A). By default E2 path is used for reactive power calculation based on current I1. **11. Apparent When POR/BOR, RSTn pin reset or WDT overflow reset occurs, these registers are re

11. Apparent Power Calculation

11. Apparent power calculation

11. Apparent power calculation

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Table 10-11 Functions of E2 Path

10.12.1. Active Power Calculation and Calibration

In the V98XX, E1 path always calculates active power based on current I1. And when DBLEN is set to 1, E2 path is also used to calculate active power based on current I2.

As illustrated in the above figure, after being filtered by the high-pass filter (HPF), the current and voltage multiply each other. Then, the product is input to the low-pass filter (LPF) to remove the harmonics and the ripples caused by the noise, and the output of the LPF is the raw active power. This raw power is gain calibrated and then offset calibrated to acquire the instantaneous active power that is stored in the registers DATAIP (0x10D1, for active power calculated in E1 path) and DATAIQ (0x10D2, for active power calculated in E2 path). The instantaneous active power will be averaged to get the average active power that is stored in the registers DATAP (0x10D6, for active power in E1 path) and DATAQ (0x10D7, for active power in E2 path). The content of all the registers are in the form of 32-bit 2'-complement, and they will be reset to their default states when POR/BOR, RSTn pin reset or WDT overflow reset occurs. **1.12.1. Active Power Calculation and Calibration

V(t) from HPF** $-\frac{c_1}{2}$ **and** $\frac{c_2}{2}$ **and** $\frac{c_3}{2}$ **and** $\frac{c_4}{2}$ **and** $\frac{c_5}{2}$ **and** $\frac{c_6}{2}$ **and** $\frac{c_7}{2}$ **and** $\frac{c_8}{2}$ **and** $\frac{c_7}{2}$ **and** $\frac{c_8}{2}$

Users can configure the registers SCP (0x10E8) and SCQ (0x10E9) for gain calibration over the range of -∞~+49.9%, and the registers PARAPC (0x10ED) and PARAQC (0x10EE) for offset calibration over the range of -50%~+50%. The content of these registers are in the form of 32-bit 2'-complement. When POR/BOR, RSTn pin reset or WDT overflow reset occurs, all the registers are reset to their default states.

10.12.2. Reactive Power and Calibration

By default the V98XX supports calculating active and reactive power based on current I1.

Figure 10-11 Signal Processing for Reactive Power Calculation and Calibration

As illustrated in the above figure, current I1, filtered by the high-pass filter (HPF), is input into a digital integrator to shift the phase by 90° (the integrator introduces an extra gain of 1.568 that can be eliminated via gain calibration). The filtered current signal is sent to the multiplier together with voltage to multiply each other. Then, the product is input to the low-pass filter (LPF) to remove the harmonics and the ripples caused by the noise, and the output of the LPF is the raw reactive power. This raw power is gain calibrated and offset calibrated to acquire the instantaneous reactive power, which is stored in the register DATAIQ (0x10D2, for reactive power calculated in E2 path). The instantaneous reactive power will be averaged to get the average reactive power, which is stored in the register DATAQ (0x10D7, for reactive power in E2 path). The content of the registers are in the form of 32-bit 2'-complement, and they will be reset to their default states when POR/BOR, RSTn pin reset or WDT overflow reset occurs.

Users can configure register SCQ (0x10E9) for gain calibration over the range of $-\infty$ ~+49.9%, and register PARAQC (0x10EE) for offset calibration over the range of -50%~+50%. Both registers are in the form of 32-bit 2'-complement. When POR/BOR, RSTn pin reset or WDT overflow reset occurs, both registers are reset to their default states.

10.13. Energy Accumulation and CF Pulse Output

The V98XX supports energy accumulation and energy-to-pulse conversion. By default this function is disabled. Users can set bit EGYEN (bit3 of PMCtrl4, 0x287D) to 1 to enable energy accumulation and energy-to-pulse conversion.

Figure 10-12 Energy Accumulation and CF Pulse Output

10.13.1. Energy Accumulation

In E1 path, positive and negative active powers are accumulated into the energy accumulators according to their signs; for example, positive active power is accumulated into PPCNT ($0x10F0$), and negative active power is accumulated into NPCNT (0x10F1). Besides, other data, such as I1 current RMS or a constant (preset in the register DATACP, 0x10FC), also can be selected to be accumulated into PPCNT

via configuring bits PSEL1~PSEL0 (bit[1:0] of PMCtrl4, 0x287D) when the chip is used for low power applications.

In E2 path, positive and negative active/reactive powers are accumulated into the energy accumulators according to their signs; for example, positive power is accumulated into PQCNT (0x10F6), and negative power is accumulated into NQCNT (0x10F7).

When MTCLK frequency is 3.2768MHz, 1.6384MHz or 819.2kHz, the energy accumulation frequency is 12.8kHz. When MTCLK frequency is 32768Hz, the energy accumulation frequency is 2979Hz.

The energy accumulators are of actual 42-bit length. But only the higher 32 bits are readable; and only the higher 32 bits are valid for write operation and the 10 least significant bits are padded with 0s in write operation. When POR/BOR, RSTn pin reset or WDT overflow reset occurs, all the energy accumulators are reset to default values, 0s.

		only the nigher 32 bits are valid for write operation and the 10 least significant bits are padded with 0s in write operation. When POR/BOR, RSTn pin reset or WDT overflow reset occurs, all the energy
		accumulators are reset to default values, 0s.
		Table 10-12 Register Configuration for Energy Accumulation
Register	Bit	Description
PMCtrl4 0x287D	Bit3 EGYEN	To enable energy accumulation and energy-to-pulse conversion. 0: disable; 1: enable.
	Bit[1:0]	To select the source for positive active energy accumulation in E1 path. 00/11: active power calculated based on current I1;
	PSEL1~PSEL0	01: I1 current RMS; 10: a constant preset in the register DATACP (0x10FC).
10.13.2.		Energy Pulse Generation and CF Pulse Output When energy accumulation and energy-to-pulse conversion is enabled, the energy will be accumulated at a certain rate. Preset a threshold in the register GATEP (0x10F4, for active energy accumulation in E1 path) or GATEQ (0x10FA, for active/reactive energy accumulation in E2 path), and when the content of energy accumulators in E1 or E2 path is higher than the preset threshold, the energy accumulator overflows, an energy pulse is generated, the energy pulse counter increments by 1, and a value equal to the threshold is subtracted from the energy accumulator.
CFCtrl, 0x287E).		When a low signal is input, users can reduce the energy threshold to increase the pulse generation rate to speed up energy calibration via configuring bits CFQR1~CFQR0 and CFQ1~CFQ0 (bit[7:4] of

Table 10-12 Register Configuration for Energy Accumulation

10.13.2. Energy Pulse Generation and CF Pulse Output

When CF pulse output is enabled, one CF pulse will be output every 2 counts of the pulse counter. When MTCLK frequency is 3.2768MHz, the maximum CF pulse output frequency is 6.4kHz, and the pulse width is configurable via bits CFWD (bit[5:4] of CRPST, 0x287F) and by default the width is 80ms.

In the V98XX, four pins, CF1, P9.5/CF2, P9.6/CF1 and P1.3/CFx, are used for CF pulse output.

- The pin CF1 is used for pulse output of E1 path only;
- When bit5 and bit6 of the register P9FS (SFR 0xAD) are set to 1s, the ports P9.5 and P9.6 are used

for CF pulse output of E1 and E2 path respectively;

When the register P13FS ($0x28C7$) is set to $0x01$, the port P1.3 is used for CF pulse output of E2 path; when the register is set to 0x04, the port P1.3 is used for CF pulse output of E1 path.

When bit CFWKEN (bit2 of IOWK, SFR 0xC9) is set to 1, CF pulse output can wake up the system from Sleep. By default CF pulse output can wake up and reset the system to OSC state. But when bit IORSTN (bit0 of IOWK, SFR 0xC9) is set to 1, this event can wake the system only but not reset the system. In this condition, after wakeup, the CPU keeps on executing the codes, and all circuits goes back where they were before sleeping, except that bits of SysCtrl (SFR 0x80), SLEEP1, SLEEP0, FWC and FSC, are cleared. When bits RTC/CF (bit2 of Systate, SFR 0xA1) and CFWK (bit3 of IOWKDET, SFR 0xAF) are read out as 1s, it indicates the system was woken up by CF pulse output.

Table 10-13 Configurations for Energy Pulse Generation Rate and CF Pulse Output

10.14. No-Load Detection

The V98XX supports no-load detection on both E1 and E2 paths. By default this function is disabled, but users can enable it via configuring bits CRPENR and CRPEN (bit7 and bit6 of PMCtrl4, 0x287D).

There is an anti-creeping accumulator in the no-load detection circuit. When no-load detection is enabled, 1s are accumulated in this register constantly. When MTCLK frequency is 3.2768MHz, 1.6384MHz or 819.2kHz, the accumulation frequency is 12800Hz; and when MTCLK frequency is 32768Hz, the accumulation frequency is 2979Hz.

When no-load detection is enabled, constant 1s are accumulated into the embedded anti-creeping accumulator, and the energy accumulator in E1 or E2 path accumulates active or reactive power or a power constant. Preset a threshold for no-load detection in register GATECP (0x10F5) or GATECQ (0x10FB), and a threshold for energy-to-pulse conversion in register GATEP (0x10F4) or GATEQ (0x10FA). Compare the accumulation rate. If the energy accumulator overflows sooner, the anti-creeping accumulator is cleared, and E1 or E2 path starts to meter energy. Otherwise, E1 or E2 path enters creeping state. Users can read bit CRPST or CRPSTR (bit7 or bit6 of CRPST, 0x287F) to detect the state of the path.

When POR/BOR, RSTN pin reset or WDT overflow reset occurs, the mentioned threshold registers are reset to their default values, 0s.

The energy accumulators are of actual 42-bit length, but the threshold registers for energy-to-pulse conversion are of 32-bit length. So, the threshold registers will be padded with a string of 10 0s on the right to work as 42-bit registers.

10.15. Line Frequency Measurement

The V98XX supports line frequency measurement.

Figure 10-13 Signal Processing for Line Frequency Measurement

In the line frequency measurement circuit, the voltage signal, filtered by the high-pass filter, is input to a band-pass filter (BPF), which has a 50Hz center frequency with 25dB attenuation at 150Hz, for signal processing. The output signal from the BPF is detected for zero-crossing. The average number of the samples of the signal in 16 cycles is equal to the value of the register DATAFREQ (0x10FD). Then, the line frequency can be calculated via the following equation:

$$
f = \frac{f_{ADC}}{FRQ}
$$

Equation 10-6

where, *f* is the line frequency to be measured; *FRQ* is the content of register DATAFREQ (0x10FD) in the form of decimal.

The line frequency register is a 16-bit, unsigned register. When POR/BOR, RSTn pin reset or WDT overflow reset occurs, this register is reset to its default state. The measurement resolution is 0.05Hz/lsb, and the measurement range is over 35~75Hz. When MTCLK frequency is 3.2768MHz, this register is updated in 320ms, and is settled in 500ms.

Note: When MTCLK frequency is lowered to 819.2kHz, the sampling frequency of the enabled band-pass filter in the RMS calculation circuit is changed to 800Hz and the center frequency is changed to 12.5Hz, which has a greater attenuation on 50Hz signals and will reduce the accuracy of the RMS calculation and line frequency measurement. So, if MTCLK frequency is reduced to 819.2kHz, users must disable energy accumulation, CF pulse output and no-load detection, and then configure this register to 0x911D3C9C.

10.16. Measuring Various Signals in M Channel

10.16.1. Architecture of M Channel

The M Channel can be used to measure the ground, temperature, battery voltage and external voltage signals. As illustrated in the following figure, there is only one ADC in M Channel, so users must configure registers to use this channel to measure one signal at a time.

Figure 10-14 M Channel Architecture

Figure 10-15 Signal Processing in M Channel

There are three data registers of M Channel, DATAOM (0x10CE) for raw waveform of the various signal input, DATADM (0x10CF) for instantaneous DC component of the signal, and DATAADM (0x10D0) for average DC component of the signal. The content of these registers are in the form of 32-bit 2' complement. When POR/BOR, RSTn pin reset or WDT overflow reset occurs, these registers are reset to their default states. nere are three data registers of M Channel, DATAOM (0x10CE) for raw waveform of the various

tr, DATAOM (0x10CE) for instantaneous DC component of the signal, and DATAOM (0x10CE)

rage DC component of the signal. The conte

In 50Hz power grid, when MTCLK frequency is 3.2768MHz, DATAOM is updated in 0.3ms and settled in 10ms; DATADM is updated in 20ms and settled in 70ms; DATAADM is updated in 1.28s and settled in 3s. If MTCLK frequency is divided by a coefficient K, the update and settle time is K times of that for 3.2768MHz MTCLK frequency.

10.16.2. Measuring Temperature

M Channel is used to measure temperature. The temperature measurement range is over $-40 \sim +85^{\circ}$ C with a measurement error of ± 1 °C.

It is recommended to measure temperature following steps:

- 1. Enable M Channel ADC: ADCMPDN=1 (bit3 of CtrlADC6, 0x2864). It is mandatory to enable BandGap circuit before M Channel ADC;
- 2. Configure the register CtrlADC5 (0x2863) as follows:
	- To disable the internal resistive divider: $RESDIV=0$ (bit4);
	- To enable M Channel to measure temperature: MEAS $<$ 2:0 $>$ = 001 (bit[2:0]).
- 3. Set bit MADCHOPN (bit0 of CtrlM, 0x2865) to 1 to stop removing DC offset in M Channel ADC;
- 4. Enable the sampling circuits and power/RMS calculation circuits: GT=0 (bit7 of IDET, 0x2886);
- 5. Configure the register PMCtrl1 (0x2878) as follows:
	- Set bit ONM (bit3) to 1 to enable digital signal input to M Channel for digital signal processing;
	- Set bit PREN (bit4) to 1 to enable digital signal processing.
- 6. Wait for 70ms (*fMTCLK*=3.2768MHz) or 280ms (*fMTCLK*=819.2kHz), and then read the register DATADM (0x10CF) and calculate the nominal temperature T' (in unit of $^{\circ}$ C):

$$
T' = \frac{B \times (D \times \frac{x_0}{2^{16}} + C)^{\frac{1}{2}} - A}{E}
$$
 Equation 10-7

where x_0 is the reading of register DATADM (in hexadecimal); $A/B/C/D/E$ is the parameters of the temperature curve, which can be read in bytes located at addresses 0x420~0x433 (in small endian format). There are another two bytes used for the checksum.

- 7. Calibrate temperature:
	- There is a constant error ΔT between the nominal temperature T' and the actual temperature T:

$$
\Delta T = \frac{x_1}{10}
$$
 Equation 10-8

where x_1 is the content of bytes located at addresses 0x480 \sim 0x481 (There are another two bytes used for the checksum.) (in hexadecimal, and in small endian format), 10 times of the actual temperature error ΔT. The unit of ΔT is 0.1 °C.

Calculate the actual temperature according to the following equation:

 $T = T' + \Delta T$

Equation 10-9

10.16.3. Measuring Battery Voltage and External Voltage

In the V98XX, pin BAT can be used to input battery voltage or external voltage signals to be measured, and the voltage signal must be over the range of -200mV~3.8V; pin UM, M0, M1 or M2 can be used to input external voltage signals to be measured, and the voltage signal must be over the range of - 200mV~3.4V. the checksum.) (in hexadecimal, and in small endian format), 10 times of the actual temperator.

The unit of AT is 0.1 °C.

The unit of AT is 0.1 °C.

The value of the following equation:

The value of the state is expect

It is recommended to measure the battery voltage or external voltage signals following steps:

- 1. Enable M Channel ADC: ADCMPDN=1 (bit3 of CtrlADC6, 0x2864). It is mandatory to enable BandGap circuit before M Channel ADC;
- 2. Configure the register CtrlADC5 (0x2863) as follows:
	- To configure the internal resistive divider:
		- \blacklozenge When the input voltage signal is over the range of -200mV \sim 1.1V, it is mandatory to set RESDIV=0 (bit4);
		- When the input voltage signal is over the range of $1.1\vee \sim 3.8\vee$ (for BAT) or $1.1\vee \sim 3.4\vee$ (for UM/M0/M1/M2), it is mandatory to set either bit GDE4 or bit RESDIV to 1;

To enable M Channel to measure battery voltage or external voltage signals.

- 3. Set bit MADCHOPN (bit0 of CtrlM, 0x2865) to 1 to stop removing DC offset in M Channel ADC;
- 4. Enable the sampling circuits and power/RMS calculation circuits: GT=0 (bit7 of IDET, 0x2886);
- 5. Configure the register PMCtrl1 (0x2878) as follows:
	- Set bit ONM (bit3) to 1 to enable digital signal input to M Channel for digital signal processing;
	- Set bit PREN (bit4) to 1 to enable digital signal processing.

Wait for 10ms (f_{MTCLK} =3.2768MHz) or 40ms (f_{MTCLK} =819.2kHz), and then read the register DATAOM (0x10CE) and RESDIV configuration, then calculate the amplitude of the voltage signal V_{DC} (in unit of mV):

When the voltage signal is over the range of -200mV \sim 1.1V:

$$
V_{DC} = \frac{\frac{X_R}{2^{16}} + 198.42}{27210}
$$

When the voltage signal is over the range of $1.1V \sim 3.8V$ (for BAT) or 3.4V (UM/M0/M1/M2), and RESDIV=1:

$$
V_{DC} = \frac{\frac{x_R}{2^{16}} + 50.693}{5959.9}
$$

Equation 10-11

Equation 10-10

Because there are 30kΩ resistors in the internal resistive divider network, this network consumes power:

$$
P = U_D \times I_D = V \times \frac{V}{R1 + R2} = \frac{V^2}{30}
$$

Equation 10-12

When the voltage signal is over the range of $1.1V~3.8V$ (for BAT) or 3.4V (UM/M0/M1/M2), and RESDIV=0:

$$
V_{DC} = \frac{\frac{X_R}{2^{16}} + 21.034}{7118.3}
$$

Equation 10-13

In the above equations, x_R is the content of register DATAOM ($0x10CE$).

10.17. Initializing Energy Metering Architecture

To ensure the performance of the energy metering architecture, it must be initialized as follows:

- 1. Clear the bits CRPEN, CFEN and EGYEN (bit5~bit3 of PMCtrl4, 0x287D) to disable energy accumulation, CF pulse output and no-load detection; clear the bit PREN (bit4 of PMCtrl1, 0x2878) and bits ONx (bit3~bit0 of PMCtrl1, 0x2878) to disable the signal input to Channel I1/I2/U/M and stop the digital signal processing. Because there are 30kΩ resistors in the internal resistive divider network, this network compower:
 $P = U_p \times I_p = V \times \frac{V}{R1 + R^2} = \frac{V^2}{30}$ Equation 10-12

Then the voltage signal is over the range of 1.1V~3.8V (for BAT) or
- 2. Enable the ADCs.
- 3. When *fADC* is 819.2kHz, write 0x889374BC to the register PARABPF (0x10EF); When *fADC* is 204.8kHz, write 0x911D3C9C to the register PARABPF (0x10EF).
- 4. Write 1 to bit PREN (bit4 of PMCtrl1, 0x2878) to enable power and RMS calculation.
- 5. Wait for 70ms (*fADC*=819.2kHz) or 250ms (*fADC*=204.8kHz) until the registers for waveform registers are read out as 0s, and then clear the read/write buffer registers located at addresses 0x2880~0x2885, and clear the registers located at addresses 0x1059~0x106A.
- 6. Configure the calibration registers (except the PARABPF and current detection threshold register).
- 7. Access to the energy metering control registers:
	- Configure the bit SELI (bit5 of PMCtrl1, 0x2878) to switch the current channels.
	- Configure the bit PHCEN (bit6 of PMCtrl1, 0x2878) to enable phase compensation, and configure the registers PHCCtrl1 (0x287B), PHCCtrl2 (0x287C) and bits IBPHC and IAPHC (bit[3:0] of CRPST, 0x287F) to set which and how the signal to be delayed.

- Configure the digital PGA gain for current and voltage signals.
- Configure the bit DBLEN (bit4 of PMCtrl3, 0x287A) to select the function of E2 path.
- Configure the bits LPFEN and BPFEN (bit5 and bit6 of PMCtrl3, 0x287A) to enable the low-pass filter and band-pass filter.
- Configure the bits PSEL1 and PSEL0 (bit1 and bit0 of PMCtrl4, 0x287D) to select the signal to be accumulated to the positive energy accumulator in E1 path.
- Configure the register CFCtrl (0x287E) for CF pulse output.
- Write 1s to bit6 and bit7 of PMCtrl4 (0x287D) to enable no-load detection in E1 and E2 paths.
- 8. Write 1s to the bits ONx (bit3~bit0 of PMCtrl1, 0x2878) to enable the signal input to Channel I1/I2/U/M.
- 9. Wait for 250ms (*fADC*=819.2kHz), or 900ms (*fADC*=204.8kHz).
- 10. Write the stored values of the energy accumulators and energy pulse counters into themselves. If the values are 0s, it is equal to clearing the registers.
- 11. Read of the threshold registers for energy-to-pulse conversion and no-load detection. If the value is anomaly, reconfigure the registers.
- 12. Configure registers to enable CF pulse interrupt (optional).
- 13. Write 1s to the bits CRPEN, CFEN and EGYEN (bit5~bit3 of PMCtrl4, 0x287D) to enable energy accumulation, CF pulse output and no-load detection.

10.18. Calibration

10.18.1. Registers for Meter Calibration

Table 10-15 Registers for Meter Calibration

10.18.2. Equations for Calibration

1. Equation for current/voltage RMS registers.

 $RMS = V \times G \times K$

Equation 10-14

where, *V* is the RMS value of the input signal (mV); *G* is the gain; and *K* is a constant, 1.8117×10^9 .

2. Equation for power registers.

 $P = Vi \times Gi \times Vv \times Gv \times B \times C$

Equation 10-15

where, *Vi* and *Vv* are the input current and voltage; *Gi* and *Gv* are the gains for current and voltage respectively; C=*cosθ* for active power calculation, C=sinθ for reactive power calculation; *B* is a coefficient, 1.5413×10^9 for active power calculation or 2.4167×10^9 for reactive power calculation.

3. Equation for ratio factor of RMS and power.

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The value acquired by [Equation 10-14](#page-128-0) or [Equation 10-15](#page-128-1) is the theoretical value of the register of the RMS or power. It must be multiplied by a ratio factor to get the actual value (accurate to the second decimal place).

$$
D = \frac{V_{n}}{Value}
$$
 Equation 10-16

where, *Value* is the theoretical value of the registers acquired by [Equation 10-14](#page-128-0) or [Equation 10-15;](#page-128-1) *D* is the ratio factor; and *Vⁿ* is the rated voltage/current/power.

4. Equation for registers for phase compensation.

Please note that phase compensation must be executed after power calibration.

At a lower power factor (PF), the phase angle error can cause greater energy metering error. So generally, the phase angle error is calibrated at PF=0.5L to ensure the metering accuracy. When PF=0.5L, users can use a simple equation as follows to calculate the value N.

> $N = Round(\frac{3011}{3})$ $rac{1}{2} \times E \times \frac{f_{smpl}}{819200}$ 819200

) Equation 10-17where,

N is the value, signed, to be set to the phase compensation control registers to correct the phase angle error. A positive N indicates that current signal must be delayed, so "0" must be set to the sign bit; a negative N indicates that the voltage signal must be delayed, so "1" must be set to the sign bit; ease note that phase compensation must be executed after power calibration.

a lower power factor (PF), the phase a[ng](#page-128-1)le error can cause greater energy metering entrally, the phase angle error is calibrated at PF=0.5L to e

E is the energy metering error displayed in LCD screen of the calibration equipment;

fsmpl is the sampling frequency of the phase compensation circuit, Hz.

5. Equation for energy accumulation threshold.

 $PGAT = {P \times T \times 6400 \over 1024}$

Equation 10-18

where *P* is the power calculated by Equation 10-15; *T* is a time constant acquired via the equation:

PulseConstant × U_n × I_n $T = \frac{3600 \times 1000}{T}$

Equation 10-19

6. Equation for the gain calibration registers.

 $\frac{1}{1+e}$ $\frac{1}{1+e} - 1$ + S₁($\frac{1}{1+e}$ $S = 2^{31}(\frac{1}{111} - 1) + S_1$

Equation 10-20

where, *S* is the content to be set in the registers for gain calibration of active/reactive power or current/voltage RMS, in the form of 2'-complement; *S¹* is the original value of the registers; *e* is the error: when this equation is used for power gain calibration, *e* is equal to the error displayed in LCD screen of the calibration equipment (*E*); when this equation is used for RMS gain calibration, *e* is equal to the error (Eu/Ei) calculated by the following equations:

$$
E_{\mathsf{u}} = \frac{U_1 - U_n}{U_n}
$$

Equation 10-21

$$
E_i = \frac{I_1 - I_b}{I_b}
$$

Equation 10-22

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where *U1/I¹* is the voltage/current RMS displayed in LCD screen of the meter to be calibrated, *Uⁿ* is the rated voltage, and *I^b* is the base current.

7. Equation for power offset calibration registers.

$$
C = a\% \times E_1 \times P
$$

where E_1 is the error displayed in LCD screen of the calibration equipment when $a\%I_b$ is applied at power factor 1.0; generally, a=1; and *P* is the power calculated by [Equation 10-15.](#page-128-1)

Equation 10-23

8. Equation for no-load detection threshold registers.

Generally, the period for the first pulse output is used as the threshold for no-load detection, so the threshold can be calculated as follows:

> GATECP = $T' \times \frac{1}{2}$ $\frac{1}{2} \times f_{overflow} = \frac{3600 \times 1000}{PulseConstant \times 1}$ $\frac{3600\times1000}{PulseConstant\times U_n\times\frac{1}{2}I_S}\times\frac{1}{2}$ 2 Equation 10-24where,

Un: rated voltage;

I_s: starting current. Generally, I_s=0.4%I_b, and $\frac{1}{2}$ I_s is used for no-load detection;

foverflow: accumulation frequency of the energy accumulator. When *fMTCLK*=3.2768MHz, *foverflow*=12800Hz; when *fMTCLK*=32768Hz, *foverflow*=2979Hz.

10.18.3. Steps for Calibration

10.18.3.1. Parameters Configuration

Users must determine the following parameters when designing an energy meter:

- Parameters for a meter, including basic current, rated voltage, pulse constant and accuracy class.
- Parameters for design, including the current and voltage RMS when rated current and rated voltage are applied. Vangotech
- The analog PGA gains of the current and voltage channels.
- The ratio factor (*D*) of RMS and power calculated via Equation 10-16.
- The threshold for energy-to-pulse conversion calculated via Equation 10-18.
- The threshold for no-load detection calculated via Equation 10-24.

When the above parameters are determined, no changes should be done to them.

10.18.3.2. Calibrating Active Energy

1. Gain calibration

At power fact of 1.0, apply 100% U_n and 100% I_b to the calibration equipment.

Before calibration, read the error displayed in LCD screen of the calibration equipment (*E*), and read the value of the gain calibration register (SCP, 0x10E8), *S1*, and then calculate the value for gain calibration via [Equation 10-20](#page-129-2) and write it to the register SCP (0x10E8). After having written, if the error displayed in LCD screen of the calibration equipment (E) is over the range of standard, indicating the difference ratio correction is succeding.

2. Phase compensation

After gain calibration of power, apply 100% I_b and 100% U_n to the calibration equipment when PF=0.5L, to correct the phase angle error between the current and voltage signals.

Clear bit[5:0] of PHCCtrl1 (0x287B) and bit[2:1] of CRPST (0x287F) or bit[5:0] of PHCCtrl2 (0x287C) and bit[4:3] of CRPST (0x287F), and then write the values calculated by Equation 10-17 to the register. If N is positive, the sign bit is "0"; if N is negative, the sign bit is "1".

3. Offset calibration

Apply 5%I_b or 2% I_b and 100%U_n to the calibration equipment when PF=1.0. Read the error (E) displayed in LCD screen and calculate the value for power offset calibration by Equation 10-23, and write them to the registers for power offset calibration. ear out also at the [c](#page-130-1)ontent in t[h](#page-129-3)e LCD screen of the calibration equipment (U₁ is the product the register SCU (0X10FA).

United 33 of CRPST (0X287F), and then write the values calculated by Equation 10-17 to the respect

10.18.3.3. Calibrating Current RMS

- 1. Clear the register SCI1 (0x10EB).
- 2. Apply 100% I_b to the calibration equipment at PF=1.0.
- 3. Read the current RMS I_1 shown in the LCD screen of the calibration equipment (I_1 is the product of the value of the gain calibration register and the coefficient D).
- 4. Calculate the value to gain calibrate the current signal of Channel I1 via Equation 10-20.

Note: When the current through the energy meter is less than the starting current, the current RMS I_1 is not shown in the LCD.

10.18.3.4. Calibrating Voltage RMS

- 1. Clear the register SCU (0x10EA).
- 2. Apply 100% U_n to the calibration equipment.
- 3. Read the voltage RMS U₁ shown in the LCD screen of the calibration equipment (U₁ is the product of the value of the gain calibration register and the coefficient D).
- 4. Calculate the value to gain calibrate the voltage signal of Channel U via [Equation 10-20.](#page-129-2)

11. Interrupt

When POR/BOR, RSTn pin reset, WDT overflow event, power recovery event, IO/RTC wakeup event or debugging event occurs, the interrupt control module is reset to its default state.

CLK1 provides clock pulses for the interrupt control module, so when the system enters Sleep or Deep Sleep state, the interrupt control module stops running to save power. Each extended interrupt can be gate controlled independently via configuring register PRCtrl1 (0x2D01).

11.1. Interrupt Sources

In the V98XX 41 events can trigger interrupts:

- 4 IO interrupts on low or high-to-low transitions;
- 4 transmitter data output interrupt of UART, and 2 transmitter data output interrupt of enhanced UART;
- 4 receiver data input interrupt of UART, and 2 receiver data input interrupt of enhanced UART;
- 4 timer overflow interrupts;
- 3 timer capture interrupts (TimerA);
- 2 overflow interrupt of enhanced UART;
- 2 CF pulse output interrupts;
- 1 pulse per second (PPS) output interrupt;
- 1 RTC illegal data interrupt;
- 1 zero-crossing interrupt;
- 1 power-down interrupt;
- 1 GPSI illegal data interrupt;
- 1 GPSI transmit interrupt;
- 1 comparator interrupt;
- 1 REF leakage interrupt.

In the V98XX the interrupts triggered by peripheral events are called "*Extended Interrupt"*. They are named after the polling sequence; for example, Interrupt 8 is named because the polling sequence of the extended interrupt handler located at 43h is 8. Additionally, an extended interrupt may be triggered by more than one event (interrupt sources); for example, both transmitter data output interrupt and receiver data input interrupt of UART2 can trigger the program execution to service the interrupt handler located at 43h (Interrupt 8). **Example 11 Constant Con**

Take Interrupt 8 as an example to introduce how to trigger an interrupt, service and clear the interrupt flag, and detect the event that triggers an extended interrupt. Only when the global enable bit IE.7 and the enable bit for Interrupt 8 (EIE.0) is set to 1, will Interrupt 8 be triggered if any one enabled peripheral event occurs and the flag bits of Interrupt 8 and the interrupt event is set bit. The program has to detect the interrupt source depending on the flags and enable bits of the peripheral event when the program enters to the interrupt subroutine located at address 43h. The processor can respond to the interrupt event by polling or interrupt handling. When an extended interrupt is responded, the program must clear the flag of the peripheral event firstly, and then the flag of Interrupt 8.

In the V98XX, there are two tiers of interrupts: Interrupt Priority 1 and Interrupt Priority 0. Registers IP (SFR 0xB8) and EIP (SFR 0xF8) can configure the priority of the interrupts. Interrupt Priority 1 takes precedence over Interrupt Priority 0. In addition to an assigned priority level (1 or 0), each interrupt has a polling sequence. An interrupt with a small polling sequence number means that it must be serviced firstly when two interrupts of the same tier occur simultaneously. If two interrupts of different priority occur, the one of Interrupt Priority 1 is serviced firstly. Only an interrupt of higher priority level can break the service routine of the interrupt currently being serviced; when the new interrupt is serviced, the program will go back where it was interrupted and serve the last interrupt.

Table 11-1 Interrupt Sources

hen Keil IDE is applied, users must use Interrupt No. to check the interrupts.

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Figure 11-1 Interrupt Logic

11.2. Interrupt Control Registers

Table 11-2 IE (SFR 0xA8)

Table 11-3 EIE (SFR 0xE8)

Table 11-4 EXIF (SFR 0x91)

Table 11-5 EICON (SFR 0xD8)

Table 11-6 IP (SFR 0xB8)

Table 11-7 EIP (SFR 0xF8)

11.3. Interrupt Processing

Figure 11-2 Interrupt Processing

The preceding figure illustrates the interrupt processing in the V98XX. When an enabled interrupt occurs,

- The program jumps to the interrupt vector address to execute the interrupt service routine (ISR) of the interrupt. An ISR being executed can only be interrupted by one of the interrupt with higher priority. Each ISR ends with an *RETI* (return from interrupt) instruction, as shown as *A* in the preceding figure.
- After executing the *RETI*, the program returns to the place where it was interrupted, as if it did not leave off, to execute the next instruction that would have been executed if the interrupt had not occurred. The program always completes an instruction in progress before servicing an interrupt. If an instruction executed in progress is *RETI*, or a write operation to registers including IP SFR, IE SFR, EIP SFR, and EIE SFR, the program will complete one additional instruction before servicing the ISR.
- In the V98XX, Interrupt Priority 1 has higher priority than Interrupt Priority 0. So, the ISR of Interrupt Priority 0 only can be interrupted by the ISR of Interrupt Priority 1, as shown as B and C in the preceding figure.
- An ISR of Interrupt Priority 0 can be intruded by one of Interrupt Priority 1. When the latter one is executed, the program will return to the place at the vector address of the former one where it was interrupted to execute the ISR, and then, execute the instruction *RETI* to finish the ISR, as shown as B in the preceding figure.
- When two interrupts of the same tier (Interrupt Priority 1 or Interrupt Priority 0) occur simultaneously, the polling sequence of them is observed, as shown as D in the preceding figure.
- Interrupt latency depends on the current state of the MCU.
	- The shortest interrupt latency is equal to five instruction cycles: one to detect the interrupt, and four to perform the *LCALL* to the ISR.
	- The longest latency (equal to thirteen instruction cycles) occurs when the MCU is currently executing an *RETI* instruction followed by a *MUL* or *DIV* instruction. The thirteen instruction cycles in this case are: one to detect the interrupt, three to complete the *RETI*, five to execute the *DIV* or *MUL*, and four to execute the *LCALL* to the ISR. For an interrupt with the maximum latency, the interrupt latency is 52 (13x4) clock cycles.

To ensure that high-to-low-transition-triggered interrupts can be detected, such as IO Interrupt 0/1/2/3, the level on the corresponding ports should be held high for at least four clock cycles and then low for no less than four clock cycles. If a level-triggered interrupt occurs when the flag has not been set bit, or an interrupt with higher priority is in process which blocks the program jumping to the interrupt vector address to execute its ISR, the interrupt signal will hold until it is to be serviced.

11.4. Extended Interrupts

Table 11-8 Interrupt Events to Trigger Interrupt 8

11.4.1. Interrupt 8

Interrupt 8 can be triggered by 7 interrupt events which are listed in the following table. Bit ExInt2 (bit0 of PRCtrl1, 0x2D01) gate controls Interrupt 8.

Table 11-9 Extended Interrupt Flag (Request) Register (ExInt2IFG, 0x2840)

Table 11-10 Extended Interrupt Input Type Register (ExInt2IN, 0x2841)

These bits must be set to their default values for proper operation.

Table 11-11 Extended Interrupt Output Type Register (ExInt2OUT, 0x2842) Г

 \parallel These bits must be set to their default values for proper operation.

Table 11-12 Extended Interrupt Enable Register (ExInt2IE, 0x2843) Г

1: enable; 0: disable; X: do not care.

Table 11-13 Extended Interrupt Pending Register (ExInt2OV, 0x2844)

11.4.2. Interrupt 9

Interrupt 9 can be triggered by 8 interrupt events which are listed in the following table. Bit ExInt3 (bit1 of PRCtrl1, 0x2D01) gate controls Interrupt 9.

Table 11-15 Extended Interrupt Flag (Request) Register (ExInt3IFG, 0x2848)

Table 11-16 Extended Interrupt Input Type Register (ExInt3IN, 0x2849)

These bits must be set to their default values for proper operation.

Table 11-17 Extended Interrupt Output Type Register (ExInt3OUT, 0x284A) Γ

 \mid These bits must be set to their default values for proper operation.

Table 11-18 Extended Interrupt Enable Register (ExInt3IE, 0x284B) Г

 \mid 1: enable; 0: disable; X: do not care.

Table 11-19 Extended Interrupt Pending Register (ExInt3OV, 0x284C)

11.4.3. Interrupt 10

Interrupt 10 can be triggered by 7 interrupt/ 5 interrupt events/which are listed in the following table. Bit ExInt4 (bit2 of PRCtrl1, 0x2D01) gate controls Interrupt 10.

Table 11-21 Extended Interrupt Flag (Request) Register (ExInt4IFG, 0x2850)

1: an interrupt request occurred; 0: no interrupt request occurred; X: do not care.

A flag bit can be set to 1 only when the corresponding interrupt was enabled. When an interrupt was enabled, writing 1 to the corresponding flag bit can trigger the interrupt. Otherwise, however, cannot.

Write 0 to a bit can clear the corresponding interrupt flag.

Table 11-22 Extended Interrupt Input Type Register (ExInt4IN, 0x2851)

These bits must be set to their default values for proper operation.

Table 11-23 Extended Interrupt Output Type Register (ExInt4OUT, 0x2852)

These bits must be set to their default values for proper operation.

Table 11-24 Extended Interrupt Enable Register (ExInt4IE, 0x2853)

Table 11-25 Extended Interrupt Pending Register (ExInt4OV, 0x2854)

If an interrupt occurs again when the corresponding flag in the register ExInt4IFG has not been cleared yet, the corresponding pending bit of this register will be set to 1. The pending bit is just an indication flag, nothing to do with the interrupt. It must be cleared by the program.

11.4.4. Interrupt 11

Interrupt 11 can be triggered by 7 interrupt events which are listed in the following table. Bit ExInt5 (bit3 of PRCtrl1, 0x2D01) gate controls Interrupt 11.

enabled. Writing of illegal data or transmit completion will trigger interrupt to CPU.

Table 11-27 Extended Interrupt Flag (Request) Register (ExInt5IFG, 0x28A2)

1: an interrupt request occurred; 0: no interrupt request occurred; X: do not care.

A flag bit can be set to 1 only when the corresponding interrupt was enabled. When an interrupt was enabled, writing 1 to the corresponding flag bit can trigger the interrupt. Otherwise, however, cannot.

Write 0 to a bit can clear the corresponding interrupt flag.

Table 11-28 Extended Interrupt Input Type Register (ExInt5IN, 0x28A3)

These bits must be set to their default values for proper operation.

Table 11-29 Extended Interrupt Output Type Register (ExInt5OUT, 0x28A4)

Table 11-30 Extended Interrupt Enable Register (ExInt5IE, 0x28A5)

1: enable; 0: disable; X: do not care.

Table 11-31 Extended Interrupt Pending Register (ExInt5OV, 0x28A6)

If an interrupt occurs again when the corresponding flag in the register ExInt5IFG has not been cleared yet, the corresponding pending bit of this register will be set to 1. The pending bit is just an indication flag, nothing to do with the interrupt. It must be cleared by the program.

12. UART/Timers

When power-on or brown out reset (POR/BOR), RSTn pin reset, WDT overflow, power recovery event, IO/RTC wakeup event or debugging reset occurs, all the timers and the UART serial interfaces are reset to their default states. In Sleep or Deep Sleep, they stop working. Each extended UART serial interface and TimerA can be gate controlled independently via configuring register PRCtrl0 (0x2D00) and PRCtrl1 (0x2D01).

12.1. Timers/Counters

The V98XX can provide users with timers listed as follows:

- TimerA, a 16-bit timer, with 3 compare/capture modules, gate controlled independently;
- Timer0, Timer1 and Timer2 of 8052 microcontroller. They work as general timers; furthermore, Timer1 can work as the baud rate generator of UART1;
- The general timer and specific baud rate generator of each extended UART serial interface (UART2/UART3(V98XX)/UART4/UART5). Each interface can be gate controlled independently. The general timer has the same function with Timer0, an overflow event of which will set the flag bit to 1, which will be cleared by executing interrupt service routine (ISR) or by polling interrupt sources, and generate an interrupt to the CPU. The specific baud rate generator has the same function with Timer1: it can be used as a general timer, an overflow event of which can set the flag bit to 1 but cannot generate an interrupt to the CPU. **2.1.** Timers/Counters

Ne V98XX can provide users with timers listed as follows:

TimerA, a 16-bit timer, with 3 compare/capture modules, [g](#page-170-0)ate controlled independently;

TimerA, a 16-bit timer, with 3 compare/capture modu

In this section, only TimerA, Timer0, Timer1 and Timer2 are introduced. The general timers in extended UART serial interfaces are introduced in "UART".

12.1.1. TimerA

TimerA is a 16-bit timer/counter, and has 4 operation modes. It has 3 compare/capture modules, and 3 configurable output units with 8 output modes. Bit TimerA (bit0 of PRCtrl0, 0x2D00) gate controls TimerA.

Figure 12-1 TimerA Architecture

Table 12-1 TimerA-Related Registers

Table 12-2 Timer A Counter/Timer Register (TAR, 0x2902~0x2903)

Table 12-3 Timer A Control Register (TACTL, 0x2900)

Figure 12-2 Operation Modes for TimerA

When either bit MC1 or MC0 is not cleared, or the clock source is active, the timer starts counting. In Up or Up/Down Mode, when the register TACCR0 is cleared, the timer stops running, and it may then be restarted counting in the up direction from zero when a non-zero value is written into the register TACCR0.

In Up Mode, when the value of the register TACCR0 is changed while the timer is running,

- if the new value is not less than the former value or current counts, the timer will count up to the new TACCR0 value, and then rolls over to 0000h;
- if the new value is less than current counts, the timer will count to the former value firstly, rolls over to 0000h, and then counts to the new TACCR0 value.

In Up/Down Mode,

- when the value of the register TACCR0 is changed while the timer is counting in the down direction, the timer continues its direction until it counts down to 0000h, and then it counts up to the new value of TACCR0 from 0000h;
- when the value of the register TACCR0 is changed while the timer is counting in the up direction:
	- if the new value is not less than the former value or current counts, the timer counts up to the new TACCR0 value before counting down;
	- if the new value is less than current counts, the timer will count to the former value firstly, counts back to 0000h, and then counts up to the new TACCR0 value.

In Continuous Mode, the output frequency is configurable, as illustrated in the following figure. This operation mode can be used to generate independent output frequencies.

Figure 12-3 Configuring Output Frequency in Continuous Mode

As illustrated in the above figure, TACCR0a and TACCR1a are the values of the registers TACCR0 and TACCR1 at the moment of Ta0 and Ta1, and TACCR0b and TACCR1b are the values of the registers TACCR0 and TACCR1 at the moment of Tb0 (Tb0=Ta0+t0) and Tb1 (Tb1=Ta1+t1), and so forth. When the interrupt is enabled (CCIE=1, Bit4, TACCTLx), an interrupt will be generated at the moment of Ta0 and Ta1 independently and at an interval (t0 or t1). The interrupt flags CCIFG (Bit0 of TACCTLx, x=0 and 1) are set bit respectively. Up to 3 independent output frequencies can be generated using all capture/compare registers. In this application, when the timer rolls over to 0000h from FFFFh, the bit TAIFG is still set.

-

an be equal to 0/1/2 to represent the TimerA Capture/Compare Module 0/1/2 control register.

0x2904~0x2905/0x2906~0x2907/0x2908~0x2909, R/W, TimerA Compare/Capture Control Register x2, TACCTLx~TACCTHx Byte Bit Default Description $Bit1$ COV 0 Capture overflow flag. In capture mode, when COV is read out as 0, the capture signal is reset, and the capture event cannot set this bit to 1. In capture mode, when COV is read out as 1, if a capture event occurs when the value of the last capture has not been read out, COV is set bit. This bit must be reset by program. Reading the captured signal cannot reset this bit. $Bit0$ $CCFG$ 0 Compare / capture interrupt flag. In capture mode: when the value of the register TAR is captured into the registers TACCR0/1/2, this flag bit will be set bit. In compare mode: when the value of the register TAR is equal to that of the registers TACCR0/1/2 (EQUx signal), this flag bit will be set bit. In Compare/Capture Module 0, when the interrupt request is responded, this flag bit will be reset automatically. In Compare/Capture Module 1/2, when the interrupt request is responded, the CCIFG flag is reset; if the corresponding enable bit is cleared, this flag bit still will be set bit, which must be cleared by program, but no interrupt will be generated. Bit1 COV In capture mode, when COV is read out as 1, if

capture event occurs when the value of the last capt

has not been read out, COV is set bit,

This bit must be reset by program. Reading t

captured signal cannot re

Figure 12-4 Output on Pin TA1 in Up Mode

Figure 12-5 Output on Pin TA1 in Continuous Mode

Figure 12-6 Output on Pin TA1 in Up/Down Mode

As illustrated in the above figures, users can configure the bits OUTMOD2, OUTMOD1 and OUTMOD0 to select the output mode. When these bits are set to 0b010/011/100/110/111, the frequency and duty cycle of the output pulse changes, generating PWM signals (pulse width modulation).

12.1.2. Timer0/Timer1/Timer2

12.1.2.1. Timer Rate Control

When the bits in CKCON (SFR 0x8E), CKCON.5, CKCON.4 and CKCON.3, are set bit, the associated timers increment by ones every clock cycle (clk). When they are cleared, the associated timers increment by ones every 12 clock cycles (clk/12). The timers are independent of each other. By default the above three bits are cleared.

Table 12-5 Bit Description of CKCON (SFR 0x8E)

12.1.2.2. Timer0/Timer1

Timer0 and Timer1 are two of three embedded timers of 8052 microcontroller. Both timers can act as a timer to count the MCU clock frequency, or act as a counter to count the input signals. Furthermore, Timer1 also can act as a baud rate generator of UART1 for serial communication.

There are 4 operation modes for Timer0 and Timer1. They are determined by TMOD (SFR 0x89) and TCON (SFR 0x88). The four modes are:

- 13-bit timer/counter (Mode 0).
- 16-bit timer/counter (Mode 1).
- 8-bit timer/counter in auto-reload mode (Mode 2).
- Split timer/counter mode (Mode 3, only for Timer0).

The SFRs associated with Timer0/Timer1 are:

- TL0 (SFR 0x8A) and TH0 (SFR 0x8C), the lower byte and higher byte of Timer0.
- TL1 (SFR 0x8B) and TH1 (SFR 0x8D), the lower byte and higher byte of Timer1.

Table 12-6 Timer0/1 Mode Control Special Function Register (TMOD, SFR 0x89)

Table 12-7 Timer0/1 Control Special Function Register (TCON, SFR 0x88)

12.1.2.2.1. Timer0/1, Mode 0

In Mode 0, Timer0 and Timer1 act as a 13-bit timer/counter. In this mode, the lower byte of Timer0/Timer1 (TLx, SFR 0x8A or SFR 0x8B) counts from 0 to 31. When it increments from 31, TLx SFR $(x=0 \sim 1)$ is cleared, and the higher byte of the timer (THx, SFR 0x8C or SFR 0x8D) increments by 1. In this mode, only 13 bits of Timer0/Timer1, Bit0~Bit4 of TLx SFR and all 8 bits of THx SFR, are active. The upper three bits of TLx SFR are indeterminate in Mode 0 and must be masked when the software evaluates the register.

Users can configure the bit (TR0 or TR1, Bit4 or Bit6 of TCON SFR) to run Timer0 or Timer1. In the V98XX, according to the value of the bit C/T (Bit6 or Bit2 of TMOD SFR), Timer0 or Timer1 can act as a timer or a counter.

When the bit GATE (Bit7 or Bit3 of TMOD SFR) is cleared or set bit, and the input signal on the pin INT0 or INT1 is active, Timer0 or Timer1 runs when TRx ($x=0$ \sim 1, TCON.4 or TCON.6) is set bit.

When the 13-bit timer increments from 0x1FFF, it rolls over to all zeros, and then the bit TF0 (TCON.5)

or TF1 (TCON.7) is set bit, and an interrupt is generated to CPU.

12.1.2.2.2. Timer0/1, Mode 1

In Mode 1, Timer0 and Timer1 act as 16-bit timers/counters. In this mode, all eight bits of the lower byte of the timers, TL0 (SFR 0x8A) or TL1 (SFR 0x8B), are active, so, TLx SFR increments from 0 to 255. When the TLx SFR increments from 255, it is cleared, and the higher byte of the timer, THx SFR (TH0 SFR or TH1 SFR), increments by 1. The timer will roll over to all zeros when the timer/counter increments from 0xFFFF.

Figure 12-7 Timer 0/1, Mode 0/1

12.1.2.2.3. Timer0/1, Mode 2

In Mode 2, only the lower byte of Timer0/Timer1 (TLx SFR, $x=0 \sim 1$) acts as an 8-bit timer/counter, while the higher byte of it (THx SFR, $x=0$ ~1) holds a value that will be loaded into TLx SFR every time TLx SFR overflows. When the value is loaded into the TLx SFR, the timer will increment from the loaded value.

For example, TH1 SFR is set to 200, and when TL1 SFR increments from 255, it rolls to 200, and recounts from 200 to 255, and then to 200, and repeats.

Figure 12-8 Timer 0/1, Mode 2

12.1.2.2.4. Timer0/1, Mode 3

In Mode 3, Timer0 becomes two completely separate 8-bit timers/counters. When Timer0 is set to work in this mode, TR0 (TCON.4) and TF0 (TCON.5) are used by TL0 SFR, but TR1 (TCON.6) and TF1 (TCON.7) are used by TH0 SFR, so Timer1 stops running as a general timer but still can be used as a baud rate generator.

When Timer0 works in Mode3, Timer1 still can be enabled via configuring its operation mode to Mode 0/1/2, but no interrupt will be generated by it, because the flag TF1 is used by Timer0. When Timer1 is configured to work in Mode 3, it stops running, but holds its counts.

Figure 12-9 Timer 0, Mode 3

12.1.2.3. Timer2

Besides Timer0 and Timer1, there is a third timer, Timer2, in 8052 microcontroller, a 16-bit timer, has a number of new functions. The modes for Timer2 are:

- 16-bit timer/counter.
- 16-bit timer/counter in capture mode.
- 16-bit timer/counter in auto-reload mode.

The SFRs associated with Timer 2 are:

- T2CON (SFR 0xC8).
- TL2 (SFR 0xCC) Lower byte of Timer2.
- TH2 (SFR 0xCD) Higher byte of Timer2.
- RCAP2L (SFR 0xCA) To capture the value of TL2 SFR when Timer 2 is configured in capture mode, or, to hold the lower byte of the loaded value when Timer 2 is configured in auto-reload mode.
- RCAP2H (SFR 0xCB) To capture the value of TH2 SFR when Timer 2 is configured in capture mode, or, to hold the higher byte of the loaded value when Timer 2 is configured in auto-reload mode.

Table 12-8 Timer2 Control Special Function Register (T2CON, SFR 0xC8)

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Table 12-9 Timer 2 Mode

12.1.2.3.1. Timer2, 16-Bit Timer/Counter Mode

In this mode, users can configure the register T2CON SFR to enable Timer2 to act as a 16-bit timer or a 16-bit counter (C/T2, T2CON.1), and to enable Timer2 to run (TR2, T2CON.2). In this mode, Timer2 increments from 0000h to FFFFh, and then rolls over to all zeros, setting the flag TF2 (T2CON.7) to 1, which generate an interrupt to CPU.

12.1.2.3.2. Timer2, 16-Bit Timer/Counter in Capture Mode

When CP/RL2 (T2CON.0) and EXEN2 (T2CON.3) are set bit, the values of TH2 SFR and TL2 SFR are captured and loaded into the registers RCAP2L SFR and RCAP2H SFR when a 1-to-0 transition of the input signal on the pin T2EX is detected. At the same time, the flag EXF2 (T2CON.6) is set bit, which will generate an interrupt to the processor if it is enabled.

Figure 12-10 Timer2, 16-bit Timer/ Counter in Capture Mode

12.1.2.3.3. Timer2, 16-Bit Timer/Counter in Auto-Reload Mode

When CP/RL2 (T2CON.0) is cleared, Timer2 acts as a 16-bit counter/timer in auto-reload mode.

In this mode, the CPU must write the reload value to the registers RCAP2L (SFR 0xCA) and RCAP2H (SFR 0xCB). When the timer increments from FFFFh, the value stored in RCAP2L will be reloaded into the register TL2 (SFR 0xCC), and the value stored in RCAP2H will be reloaded into the register TH2 (SFR 0xCD), at the same time, TF2 is set bit, which will generate an interrupt to the processor if it is enabled.

When CP/RL2 is cleared, but EXEN2 (T2CON.3) is set bit, an auto-reload event occurs when a 1-to-0 transition of the input signal on the pin T2EX is detected, at the same time, the flag EXF2 (T2CON.6) is set bit, which will generate an external interrupt to the processor if it is enabled.

Figure 12-11 Timer2, 16-Bit Timer/Counter in Auto-Reload Mode

12.2. UART

In V98XX, there are 5 active UART serial interfaces on the chip, including UART1 of 8052 microcontroller and the extended UART2 /UART3/UART4/ UART5 serial interfaces. Bits UART2 (bit4)/ UART3(bit5), UART4(bit6) and UART5(bit7) (bit4~bit7 of PRCtrl1, 0x2D01) gate controls the corresponding UART serial interfaces.

The UART serial interfaces can work in 4 modes. In Mode 0, the serial interface can only receive data on the RXD port and output shifting clock on the TXD port. In other modes, the extended UART serial interfaces can work like UART1 serial interfaces of 8052 microcontroller.

It is recommended to use extended UART interfaces for serial communication.

12.2.1. UART1

UART1 uses Timer1 to generate baud rate, and the bit SMOD1 (EICON.7) controls doubling the baud

The SFRs associated with UART1 are:

- SCON1 (SFR 0xC0) UART1 Control Register.
- SBUF1 (SFR 0xC1) UART1 Buffer Register.

Table 12-10 UART1 Control Special Function Register (SCON1, SFR 0xC0)

12.2.2. Extended UART Serial Interfaces

All the extended UART serial interfaces have the same architecture, but only UART2 has an optional 38-kHz carrier wave modulator.

In each extended UART serial interface, there are a general timer (compatible with Timer0) and a baud rate generator (compatible with Timer1). The overflow of general timer can set a flag bit which will be cleared by executing interrupt service routine (ISR) or by polling interrupt sources, and generate an interrupt to the CPU. When the baud rate generator is used as a general timer, it can set the related overflow flag to 1, but cannot generate an overflow interrupt. As an extended peripheral, there is a specific control/status register for each UART interface, which can control the baud rate, select the clock sources for the timers, disable or enable the timers, and show the overflow state of the timers.

12.2.2.1. Registers

Table 12-11 Extended UART Serial Interfaces Registers

Table 12-12 UARTx Control/Status Register (TCON2/TCON3/TCON4/TCON5)

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Table 12-13 UARTx Timers Mode Control Register (TMOD2/TMOD3/TMOD4/TMOD5)

ń

Table 12-14 UARTx Control Register (SCON2/SCON3/SCON4/SCON5)

Bit		Description
Bit1 SCON _{2.1}	TI	Transmit interrupt flag. If this flag is set bit, it indicates that the transmit data has been shifted out. In Mode0, TI is set at the end of the 8 th bit. In other modes, TI is set when the stop bit is placed on the pin TXD2. TI must be cleared by the program.
Bit ₀ SCON2.0	RI	Receive interrupt flag. If this flag is set, it indicates that a serial data has been received. In Mode0, RI is set at the end of the $8th$ bit. In Mode1, according to the state of SM2, RI is set after the last sample of the incoming stop bit. In Mode2 and Mode3, RI is set at the end of the last sample of the $9th$ bit. RI must be cleared by the program.

Table 12-15 UARTx Buffer Register (SBUF2/SBUF3/SBUF4/SBUF5)

12.2.2.2. Carrier Wave Modulation on UART2

UART2 has a 38 kHz carrier wave modulator controlled by TXD2 Type Register (Txd2FS). When bit TXD2CARRY (bit0 of Txd2FS, 0x28CF) is cleared, pin TXD2 will output modulated signals. Users can write of the carrier wave generation registers to configure the carrier wave frequency and its duty cycle:

$$
f_{CARR} = \frac{f_{MCU}}{CARRH + CARRL}
$$
 Equation 12-1
But $y_{CARR} = \frac{CARRH}{CARRL}$ Equation 12-2

where, *fCARR* is the carrier wave frequency; *fMCU* is MCU clock frequency; *DutyCARR* is the duty cycle of the carrier wave; *CARRH* is the value of registers CARRHH and CARRHL; *CARRL* is the value of registers CARRLH and CARRLL.

When the level on the pin TXD2 is low, the modulated signal is output.

Table 12-16 TXD2 Type Register (Txd2FS, 0x28CF)

Table 12-17 Carrier Wave Generation Registers

12.2.2.3. UART Modes

The UART serial interfaces can work in 4 modes via configuring the mode select bits, for example, SM1 and SM2 of the register SCON2 (0x2826).

Table 12-18 UART Modes

All the UART serial interfaces have the same architecture and functions except that:

- Only UART2 has 38-kHz carrier wave with its TXD.

UART1 uses Timer1 as its baud rate generator.

So take UART2 for an example to introduce the work modes for UART serial interfaces.

12.2.2.3.1. Mode0

In Mode0, UART2 receives data on the pin RXD2, and outputs shift clock on the pin TXD2. Data can be received as soon as the bit REN (bit4 of SCON2, 0x2826) is set bit and the bit RI (bit0 of SCON2, 0x2826) is cleared. The shift clock is activated and the UART shifts data in on each rising edge of the shift clock until eight bits have been received. The 8th bit was shifted in, and one machine cycle later, the bit RI is set bit and the reception stops until the bit RI is cleared by the program.

12.2.2.3.2. Mode1

Mode1 provides standard asynchronous and full-duplex communication. In this mode, a data frame contains ten bits: one start bit, eight bits of data, and one stop bit. When a data frame is received, the stop bit is stored in the bit RB8 (bit2 of SCON2, 0x2826). On receive and transmit operation, start with the LSB. eare. Ine smitt clock is activated and the UARIs institute can in one each range eare of the smitt end in each ten the tens and the U-this case of the program.

1. eight bits have been received. The 8¹⁰ bit was shifted

In Mode1, the baud rate is determined by the baud rate generator overflow frequency. UART2 uses a dedicated baud rate generator, which is compatible with Timer 1. When the baud rate generator overflows, it generates a clock which is then divided by 16 to generate the baud rate.

$$
BaudRate = \frac{2^{SMODx}}{32} \times Overflow
$$
 Equation 12-3

Where,

Overflow is the baud rate generator overflow frequency. As for UART1, Timer1 is the baud rate generator; as for the extended UART serial interfaces, the specific baud rate generator is used. SMODx, the value of the bit SMOD0/1, determines to double the baud rate or not.

Generally, the baud rate generator works in the mode of 8-bit timer with auto-reload. The reload value is stored in the register TH21 (0x2823), which makes the above equation for baud rate (clk/12 is used as the clock source):

$$
BaudRate = \frac{2^{SMODx}}{32} \times \frac{clk}{12 \times (256 - TH21)}
$$
 Equation 12-4

where, clk is the MCU clock, and TH21 is the reload value of the register TH21 (0x2823).

The bit T1M (TCON2.5) determines the clock source for the baud rate generator of UART2. When T1M is set bit, clk is used as the clock source:

\n
$$
\text{BaudRate} = \frac{2^{\text{SMODx}}}{32} \times \frac{\text{clk}}{(256 - \text{TH21})}
$$
\n
\n Equation 12-5\n

Users can obtain the value of TH21 via the equation:

$$
\text{TH21} = 256 - \frac{2^{\text{SMODx}} \times \text{clk}}{32 \times \text{BaudRate}}
$$

Equation 12-6

When T1M is cleared, and the baud rate is known, users can obtain the value of TH21 via the following equation:

$$
TH21 = 256 - \frac{2^{SMODx} \times \text{clk}}{384 \times \text{BaudRate}}
$$
 Equation 12-7

In Mode1, UART2 begins to transmit data after the program writing data into the register SBUF2 (0x2827). UART2 transmits data on the pin TXD2 in the following order: start bit, eight data bits (LSB first), stop bit. The bit TI (bit1 of SCON2, 0x2826) will be set bit two clock cycles after the stop bit is transmitted.

In Mode1, UART2 starts to receive data at the falling edge of a start bit received on the pin RXD2, when the REN (bit4 of SCON2, 0x2826) bit is set. To achieve this, every bit on the pin RXD2 should be sampled sixteen times at any baud rate. When a falling edge of a start bit is detected, the timer used to generate the receive clock is reset to synchronize with the received bits. To reject noise, the serial port detects the values of the three consecutive samples in the middle of each bit. Only more than two same values can decide the received data bit to be valid. This is especially true for the start bit. If the falling edge on the pin RXD2 is not verified by a majority decision of three consecutive samples, then the serial port stops receiving data and waits for another falling edge on RXD2. Model, UART2 starts to receive data at the falling edge of a start bit received on the pin RX

The REN (bitd of SCON2, Ox2826) bit is set. To achieve this, every bit on the pin RXD2 should

pled sixten thres at any baud r

When RI (bit0 of SCON2, 0x2826) is cleared, SM2 (bit5 of SCON2, 0x2826) is set bit, and the stop bit is 1 (if SM2 is cleared, the state of stop bit does not matter), the serial port will write the received byte to the register SBUF2 (0x2827), load the stop bit into RB8 (bit2 of SCON2, 0x2826), and set the bit RI to 1. Otherwise, the received data lose; they cannot load data into the register SBUF2 and the bit RB8; and the bit RI cannot be set bit.

12.2.2.3.3. Mode2

Mode2 provides asynchronous and full-duplex communication. In this mode, the data frame contains eleven bits: one start bit, eight data bits, one programmable 9th bit, and one stop bit.

When data bits are received or transmitted, start with LSB. As to the transmitting operation, the $9th$ bit is determined by the value of the bit TB8 (bit3 of SCON2, 0x2826). If the 9th bit is used as a parity bit, the value of the P bit (Bit 0 of PSW SFR) should be moved to TB8.

In Mode2, the baud rate is either clk/32 or clk/64, determined by the bit SMOD (Bit7 of TCON2, 0x2820). It can be calculated as follows:

$$
BaudRate = \frac{2^{SMODx} \times ck}{64}
$$
 Equation 12-8

In Mode2, UART2 starts transmitting data after the software writing data into the register SBUF2 (0x2827). UART2 transmits data on the pin TXD2 in the following order: the start bit, eight data bits (LSB first), the 9th bit, then the stop bit. The bit TI (bit1 of SCON2, 0x2826) is set bit when the stop bit has been transmitted.

In Mode2, receiving data begins at the falling edge of a start bit received on the pin RXD2, when the bit REN=1 (bit4 of SCON2, 0x2826). To achieve it, every bit on the pin RXD2 should be sampled sixteen times at any baud rate. When a falling edge of a start bit is detected, the timer used to generate the receive clock is reset to synchronize with the received bits. To reject noise, the serial port detects the values of the three consecutive samples in the middle of every bit. Only more than two same values can decide the received data bit to be valid. This is especially true for the start bit. If the falling edge on the

pin RXD2 is not verified by a majority decision of three consecutive samples, then the serial port stops receiving data and waits for another falling edge on RXD2.

When RI (bit0 of SCON2) is cleared, SM2 (bit5 of SCON2) is set bit, and the stop bit is 1 (if SM2 is cleared, the state of stop bit does not matter), the serial port will write the received byte to the register SBUF2 (0x2827), load the stop bit into RB8 (bit2 of SCON2), and set the bit RI. Otherwise, the received data lose; they cannot load data into the register SBUF2 and the bit RB8; and the bit RI cannot be set bit.

12.2.2.3.4. Mode3

Mode3 provides asynchronous and full-duplex communication. In this mode, the data frame contains eleven bits: one start bit, eight data bits, one programmable 9th bit, and one stop bit. When data bits are received and transmitted, start with LSB.

In Mode3, the data is transmitted or received in the same way that in Mode2. In Mode3, the baud rate generation is identical to that in Mode1. That is, Mode3 is a combination of the communication protocol in Mode2 and the baud rate generation in Mode1.

12.2.2.3.5. Multiprocessor Communication

The multiprocessor communication is enabled in Mode2 and Mode3 when the bit SM2 (bit5 of SCON2, 0x2826) is set bit. In the multiprocessor communication mode, the received 9th bit is stored in the bit RB8 (bit2 of SCON2, 0x2826), and, after the stop bit has been received, UART2 receive interrupt is activated if RB8 is set bit.

The multiprocessor communication is used to send a block of data from a master to one slave. The master first transmits an address byte that identifies the target slave. When transmitting an address byte, the master sets the 9th bit to 1; when transmitting data bytes, the master clears the 9th bit.

When SM2 is set bit, no slave can generate an interrupt when a data byte has been received. However, all slaves can generate interrupts when an address byte is received. Every slave can examine the received address byte to determine whether it is the slave being addressed. Address decoding must be done by the program during the interrupt service routine. The slave being addressed clears the bit SM2 and prepares to receive the data bytes. The slaves that are not being addressed leave the bit SM2 set and ignore the incoming data bytes. **2.2.2.3.4. Mode3**

2.2.2.3.4. Mode3

2.2.2.3.4. Mode3

2.2.2.3.4. Mode3

2.2.2.3.4. Mode3

2.2.2.3.4. Mode3

2.2.2.3.5. Multiprocessor communication is same way that in Mode2. In Mode3, the baud

2.2.2.3.5. Multiprocesso

12.3. Enhanced UART Serial Interfaces (EUART)

Besides the above general UART serial interfaces, there are two enhanced UART serial interfaces (EUART1 and EUART2) which have features as follows:

- ISO/IEC 7816-3 compliant;
- asynchronous and half-duplex communication;
- programmable baud rate;
	- re-transmitting automatically.

The EUART interface receives and transmits a data frame composed of 10 bits: 1-bit start bit (START, low level), 8-bit data (DATA, from MSB to LSB) and 1-bit check bit (CK). When the 8-bit DATA are received and transmitted, the MSB is first. Bits EUART1 and EUART2 (bit1~bit2 of PRCtrl0, 0x2D00) gate controls the corresponding enhanced UART serial interfaces.

Figure 12-12 Data Frame in EUART Communication

12.3.1. Registers

In the V98XX, the EUART related registers are located at addresses 0x2A00~0x2A05 (for EUART1) and 0x2B00~0x2B05 (for EUART2).

Table 12-20 EUART Buffer Register (DATAA/DATAB, 0x2A03/0x2B03)

Table 12-21 EUART Information Register (INFOA/INFOB, 0x2A04/0x2B04)

Table 12-22 EUART Configuration Register (CFGA/CFGB, 0x2A05/0x2B05)

than three times. For example, the program must disable the automatic re-transmitting after two failures of re-transmitting.

12.3.2. EUART Communication Timing

On EUART communication, the period for transmitting or receiving 1 bit is defined as the elementary time unit (ETU). When a data frame was transmitted, a period is needed by the receiver to check the received data before the transmitter sends another data frame. This period is defined as the guard time (GT). Generally, 1 GT is equal to 3 ETU.

Figure 12-13 EUART Communication Timing

As shown in A, the transmitter sends a 10-bit data frame to the receiver, including 1-bit START, 8-bit DATA and 1-bit CK. At the end of transmission, the receiver sends a check signal CKACK of 1 to 2 ETU length. If a high level CKACK is transmitted, it indicates the received data frame is valid; in this condition, the transmitter and receiver will remain at high state for at least 1 ETU, and then the transmitter will send the next data frame.

As shown in B, the transmitter sends a 10-bit data frame to the receiver, including 1-bit START, 8-bit DATA and 1-bit CK. At the end of the transmission, the receiver sends a check signal CKACK of 1 to 2 ETU length. If a low level CKACK is transmitted, the signal will be driven to low from high at the moment of 9.5 ETU, and then pulled high at the moment of 11.5 or 12.5 ETU, which is determined by the configuration of the bit ACKLEN (bit4 of CFG), and holds high for 0.5 ETU. Then the transmitter will send the data frame again.

EUART interfaces support half-duplex communication. When the transmitter is sending a data frame, the receive port of the transmitter receives logic "1" all the time; when the receiver sent a signal CKACK to the transmitter at the end of the data frame transmission, the receive port of the transmitter receives the CKACK.

12.3.3. EUART Baud Rate Generation

In the V98XX, each EUART has a 16-bit timer for baud rate generation, DIVLA/DIVHA and DIVLB/DIVHB. The timer counts the MCU clock cycles. When the timer overflows, the transmitter is enabled to transmit 1-bit data. The baud rate can be calculated as follows:

Baudrate =
$$
\frac{f_{MCU}}{10000h - DIV} = \frac{1}{ETU}
$$
 Equation 12-9

where, f_{MCU} is the MCU clock frequency, DIV is the preset value of the timer (DIVLA/DIVHA or DIVLB/DIVHB).

To ensure that the receiver can receive reliable data, the data receive is enabled at the moment of 0.5 ETU after the transmission started.

12.3.4. Data Transmission and Reception

By default the EUART serial interfaces stay IDLE.

12.3.4.1. Data Transmission

In the state IDLE, writing of the buffer register DATAA/DATAB (0x2A03/0x2B03) will enable data transmission. The transmission has 7 steps, each lasting 1 ETU:

- 1. transmitting the bit START (0);
- 2. transmiting 8-bit DATA, from MSB to LSB;
- 3. transmitting 1-bit CK;
- 4. reading the CKACK signal transmitted by the receiver, and then generating a transmit interrupt if the bit SDIE was set bit;
- 5. waiting state 1 (1 ETU);
- 6. waiting state 2 (1 ETU);
- 7. if a high level CKACK is transmitted by the receiver, or the automatic re-transmitting is disabled (AUTOSD is cleared, bit3 of CFGA/B, 0x2A05/0x2B05), the EUART interface gets back to IDLE state; if a low level CKACK is transmitted by the receiver, and the automatic re-transmitting is enabled, the EUART interface starts to transmit the start bit (START) of the former data frame again. **1.3.4.1. Data Transmission**

the state IDLE, writing of the buffer register DATAA/DATAB (0x2A03/0x2B03) will enable

smission. The transmission has 7 steps, each lasting 1 ETU:

transmitting the bit START (0);

transmitti

12.3.4.2. Data Reception

When the V98XX works as a slave, the EUART interface starts to receive a data frame when a 1-to-0 transition of the signal was detected. The data reception includes steps as follows, each lasting 1 ETU:

- 1. receiving the bit START (0);
- 2. receiving 8-bit DATA, from MSB to LSB;
- 3. receiving 1-bit CK;
- 4. transmitting a CKACK signal to the transmitter. If the received CK is equal to that automatically computed by the chip, or the automatic re-receiving is disabled (AUTORC is cleared, bit2 of CFGA/CFGB, 0x2A05/0x2B05), CKACK is high level; otherwise, CKACK is low level.
- 5. Transmitting the CKACK signal to the transmitter again. If the received CK is equal to that automatically computed by the chip, or the automatic re-receiving is disabled (AUTORC is cleared, bit2 of CFGA/CFGB, 0x2A05/0x2B05), CKACK is high level; otherwise, CKACK is low level. After this step, an interrupt is generated to CPU.
- 6. getting back to the IDLE state.

Figure 12-14 Data Transmission and Reception

12.3.5. EUART for Smart Card Communication

Both EUART interfaces are ISO/IEC 7816-3 compliant, so they can be used for smart card communication.

When the EUART interface is used for smart card communication, the pulse width modulation clock (PWM clock) output from the pin P9.7 will be used as the smart card clock input. The pulse width can be configured via the registers listed in the following table. Bit PWMCLK (bit7 of PRCtrl0, 0x2D00) gate controls the PWM clock generator.

Users can write of pulse width modulation clock generators to configure the PWM clock frequency and its duty cycle:

$$
f_{PWMCLK} = \frac{f_{MCU}}{PWMCLK1 + PWMCLK2}
$$
 Equation 12-10
But $y_{PWM} = \frac{PWMCLK1}{PWMCLK2}$ Equation 12-11

where, *fPWMCLK* is PWM clock frequency; *fMCU* is MCU clock frequency; *DutyPWM* is the duty cycle of PWM clock; *PWMCLK1* is the value of registers PWMCLK1H and PWMCLK1L; *PWMCLK2* is the value of registers PWMCLK2H and PWMCLK2L.

Table 12-23 Pulse Width Modulation Clock Generators

13. General-Purpose Serial Interface (GPSI)

V98XX integrates a general-purpose serial interface (GPSI) that is compliant with the I ²C protocol. When the bit "GPSI" ("bit6" of "PRCtrl0", 0x2D00) is set to '1', pins "P9.1" and "P9.2" work as the two wires of the general-purpose serial interface: **"P9.1"** for serial data (**"SDA"**), and **"P9.2"** for serial clock (**"SCL"**). When pins **"P9.1"** and **"P9.2"** is used for GPSI wires, **"P9.1"** must be configured to **"Input enabled"**, but no mandatory requirement on the output enable register of **"P9.1"**; and **"P9.2"** is **"Output enabled"** automatically.

13.1. Frame Structure

Figure 13-1 Frame Structure on SDA

As illustrated in Figure 13-1, a frame through the wire **"SDA"** is composed of some of the following parts.

- **1-bit START**: A falling edge on **"SDA"** when **"SCL"** holding **"HIGH"** sets up a START condition. This bit must be sent by Master.
- **8-bit DATA byte**: 1 bit DATA transferred on 1 SCL clock. A DATA bit is prepared on the falling edge of each SCL clock, and sampled on the rising edge of each SCL clock. The endian of byte transfer is defined by the bit **"Endian"** (**"bit4"** of **"SICFG"**, 0x2F01). 8-bit DATA byte must be followed by 1 bit **"ACK"**.
- **1-bit ACK**: The **"ACK"** bit is prepared on the falling edge of an **"SCL"** clock, and sampled on the rising edge of an **"SCL"** clock. Only the **"ACK"** bit transferred by the receiver is valid. **"HIGH"** indicates **"Not acknowledged"**; **"LOW"** indicates **"Acknowledged"**. 1-bit ACK must be preceded by 8-bit DATA.
- **1-bit STOP or RESTART**, when **"SCL"** holds **"HIGH"**, the SDA signal will generate a rising edge (**"STOP"**) or falling edge (**"RESTART"**). Preparing **"SDA"** data in the **"SCL"** falling edge, Sampling **"SDA"** data in a **"SCL"** rising edge. So, Before **"STOP"** or **"RESTART"**, SCL signal must produce a falling edge, while ensuring the SDA level on the rising edge of **"SCL"**: If users want to generate **"STOP"**, users should ensure that the SDA signal is low; If you want to generate RESTART, should ensure that the SDA is high level. STOP or RESTART must be issued by by Master device.

Bit[3:0] of register SICFG (0x2F01) defines the structure of the frame to be transmitted or received.

13.2. Serial Clock Generation

When a START condition is set up, the 16-bit timer embedded in the GPSI unit starts to count the MCU clock pulses to generate the serial clock (f_{SCL}). The f_{SCL} is defined by the following equation:

$$
f_{SCL} = \frac{f_{MCU}}{4 \times (TH + 1)}
$$

Equation 13-1

where f_{MCU} is the clock frequency for MCU operation; *TH* is the threshold preset in registers SITHH (0x2F03) and SITHL (0x2F02); *fSCL* is the serial clock (SCL) frequency, and the maximum *fSCL* is 400kHz.

13.3. Receive and Transmit Data

Figure 13-2 Receive and Transmit Data

When the V98XX communicate with other devices via GPSI, it transmits and receives data simultaneously.

The data on the wire SDA is in the format of Wire-AND, which means the data is the data from receiver and transmitter in "AND" logic, but not the state of either. The MCU can read the register SIDAT (0x2F04) and bit ACK (bit0 of SIFLG, 0x2F05) to acquire the data of the SDA. When GPSI is idle (BUSY, bit1 of SIFLG, 0x2F05, is cleared), writing of register SIDAT (0x2F04) triggers data receive and transmit.

When bit BUSY (bit1 of SIFLG, 0x2F05) is cleared, writing 0xFF or a specific data byte to be transmitted to register SIDAT (0x2F04) triggers data receive and transmit. Then bit BUSY is set to 1. After data transmit and receive, bit BUSY is cleared again, and read register SIDAT and bit ACK (bit0 of SIFLG, 0x2F05) to acquire the data from SDA.

13.4. GPSI Interrupt

When IE4=1 (bit4 of ExInt5IE, 0x28A5), EIE.3=1 (SFR 0xE8) and IE.7=1 (SFR 0xA8), a transmit interrupt will be triggered every time a frame (structure defined by register SICFG) is transmitted, and CPU will service the interrupt, read bit ACK, and prepares for the next frame transmission.

When IE5=1 (bit5 of ExInt5IE, 0x28A5), EIE.3=1 (SFR 0xE8) and IE.7=1 (SFR 0xA8), writing of registers located at addresses 0x2F01~0x2F04 when bit BUSY (bit1 of SIACK, 0x2F05) is set to 1, an illegal data interrupt will be triggered and the write operation is invalid.

SCL holds LOW on interrupt service.

13.5. For I²C Application

The GPSI is I²C compliant. When it is used for I²C application, the V98XX works as Master device to

communicate with other devices connected to the I²C bus. In this case, the starting frame is to select the target slave, of which bit[7:1] of 8-bit DATA is slave address byte, and bit0 is read/write control bit ("1" read; "0" write).

Figure 13-3 Read Operation

Figure 13-4 Write Operation

Figure 13-3 and Figure 13-4 depict read and write operation on I²C application when interrupt is enabled. For example, when the V98XX writes or reads a slave device connected on I²C bus via GPSI, it could be done following the procedure:

- 1. Write of registers SITHH/SITHL (0x2F03/0x2F02) to configure fscL;
- 2. Write of register SICFG (0x2F01) to enable transmitting START, and clear bit Endian to 0;
- 3. Write anything to register SIDAT (0x2F04) to trigger to transmit START. During transmission, bit BUSY is set to 1;
- 4. When BUSY is cleared, write of register SICFG (0x2F01) to enable transmitting DATA and ACK; write 0x01 to register SIACK (0x2F05); and then write target slave address to bit[7:1] of register SIDAT (0x2F04) and write 1 (to read) or 0 (to write) to bit0 to trigger transmitting the slave address frame. During transmission, bit BUSY is set to 1;
- 5. When BUSY is cleared, read of register SIACK (0x2F05). If it is read out as 0, the target slave device is selected;
- 6. Write of register SICFG (0x2F01) to enable transmitting DATA and ACK; write of 0x01 to register SIACK (0x2F05); and then write the content to be transmitted to register SIDAT (0x2F04) to trigger transmitting data frame. During transmission, bit BUSY is set to 1;

- 7. Repeat step 5 and 6 until all data have been transmitted;
- 8. Write of register SICFG (0x2F01) to enable transmitting STOP or RESTART;
- 9. Write anything to register SIDAT (0x2F04) to trigger transmitting bit STOP or RESTART.

The bit STOP ends a serial communication.

13.6. Registers

Table 13-2 Register to Disable or Enable GPSI

Table 13-3 GPSI Control Register (SICFG, 0x2F01)

Table 13-4 GPSI Timer Divider Registers (SITHH/SITHL, 0x2F03/0x2F02)

Table 13-5 GPSI Data Register (SIDAT, 0x2F04)

The content of this register is the 8-bit DATA byte received or to be transmitted. Writing of this register triggers receiving or transmitting data.

Table 13-6 GPSI Communication Flag Register (SIFLG, 0x2F05)

14. LCD Driver

V98XX has the LCD driver which can drive the LCD panel of 4×40 or 6×38 segments (1/3 bias) or 8×36 segments (1/3 bias or 1/4 bias). **"CLK3"**, sourced by the 32.768-kHz OSC clock, provides the LCD driver with the clock pulse. The driver is powered by the regulated voltage output from the 3.3-V LDO; the LCD bias generator composed of an internal resistor ladder generates the LCD waveform voltage; and the LCD waveform voltage level can be adjusted over the range of 2.7 V \sim 3.3 V with a resolution of 0.1 V/lsb.

When a POR/BOR, RSTn pin reset, or WDT overflow reset occurs, the LCD driver will be reset to its default state.

Figure 14-1 LCD Driver Block Diagram

14.1. Pins for LCD Driver

In V98XX, some pins are multiplexed by SEG/COM signal output, general-purpose input/output (GPIO), and analog input of M Channel or comparator CB.

When some bits of SEG Control Registers (R/W) are set to 1s, the corresponding pins are used for SEG output. In this condition, it is mandatory to configure the GPIO ports as **"Input disabled"** and **"Output disabled"** in the corresponding input and output enabled registers.

When the pins work as GPIO or analog input of M Channel or comparator CB, the corresponding bits of [SEG Control Registers \(R/W\)](#page-209-0) must be cleared to disable SEG output.

Equation 14-1

14.2. LCD Timing

In the V98XX, the CLK3, sourced by the 32.768kHz OSC clock, provides the LCD driver with clock pulse for timing generation. Generally, the crystal oscillator keeps on running until it is powered off, so the LCD driver keeps on working even in Sleep or Deep Sleep state unless CLK3 is disabled. When the crystal stops running anomaly when power is still on, the internal RC clock will become the replacement of the OSC clock to source the LCD driver until the crystal is stimulated to run again.

The CLK3 frequency is divided to generate frame frequency for the waveform. The MCU can configure bit[1:0] of LCDCtrl (0x2C1E) to select the appropriate frame frequency. By default it is 64Hz.

14.3. LCD Waveform Voltage

In the V98XX, the LCD driver is powered by the 3.3V LDO output voltage, and an internal resistor ladder is designed to generate LCD waveform voltage (VLCD). Users can adjust the waveform voltage via bits VLCD (bit2 of CtrlLCDV, 0x285E) and LDO3SEL<2:0> configurations.

$$
VLCD = [VLCD] \times \frac{[LD03SEL < 2:0 >]}{3.3}
$$

where,

VLCD is the LCD waveform voltage;

[LDO3SEL<2:0>] is the output voltage of 3.3V LDO (LDO33). [LDO3SEL<2:0>] is equal to configuration of bits LDO3SEL<2:0> (bit[5:3] of CtrlLDO, 0x2866);

[VLCD] is the configuration of bit VLCD (bit2 of CtrlLCDV, 0x285E).

Users can adjust the resistance value of each resistor in the resistor ladder of the bias voltage generation circuits via bits DRV1/DRV0 (bit[3:2] of LCDCtrl, 0x2C1E) to adjust the current through the circuits to change the lightness of the display panel. By default the resistance value is 300 kΩ.

14.4. Display RAM

In the V98XX, the display RAM located at addresses of 0x2C00~0x2C1D and 0x2C28~0x2C31 stores the LCD data. When the SEG/COM driver is enabled (setting bit7 of LCDCtrl to 1), the LCD panel displays the data immediately they are updated in the RAM. When the SEG/COM driver is disabled (clearing bit7 of LCDCtrl), the LCD panel displays nothing. When POR/BOR, RSTn pin reset or WDT overflow event occurs, the SEG/COM driver will be reset and the RAM will be cleared.

The LCD driver supports LCD panel of 1/4 duty, 1/6 duty or 1/8 duty. When bits LCDTYPE (bit[5:4] of

LCDCtrl, 0x2C1E) are cleared, an LCD panel of 1/4 Duty should be used. In this application, each byte of display RAM stores content of 2 LCD segments: lower 4 bits for Seg (n), and higher 4 bits for Seg $(n+1)$.

When bits LCDTYPE (bit[5:4] of LCDCtrl, 0x2C1E) are set to 1, an LCD panel of 1/6 Duty should be used. In this application, by default every 3 bytes of display RAM store content of 4 LCD segments. But when bit 6COMTYPE (bit6 of LCDCtrl, 0x2C1E) is set to 1, each byte of display RAM stores content of one LCD segment.

Table 14-3 RAM Byte Allocation for Segments of LCD Panel of 1/6Duty When 6COMTYPE=0

Table 14-4 RAM Byte Allocation for Segments of LCD Panel of 1/6 Duty When 6COMTYPE=1

When bits LCDTYPE (bit[5:4] of LCDCtrl, 0x2C1E) are set to 2 or 3, an LCD panel of 1/8 Duty should be used. In this application, each byte of display RAM stores content of one LCD segment.

Table 14-5 RAM Byte Allocation for Segments of LCD Panel of 1/8 Duty

14.5. LCD Drive Waveform

There are 4 resistors in series in the bias voltage generation circuit, which can be configured to work in 1/3 bias mode or 1/4 bias mode.

When an LCD panel of $1/4$ or $1/6$ duty is applied, only $1/3$ bias mode can be used.

When an LCD panel of 1/8 duty is applied, users can configure bit LCDBMOD (bit3 of CtrlBAT, 0x285C) to disable or enable one resistor in the bias voltage generation circuit to enable the LCD driver to work in 1/3 bias mode or 1/4 bias mode. **EC31**
 LCD Drive Waveform

Free are 4 resistors in series in the bias voltage generation circuit, which can be configured to $(3 \text{ bias mode} + \text{Beta Int})$ and cor $1/4$ bias mode.

Alter an LCD panel of $1/4$ or $1/6$ duty is appl

When an LCD panel of 1/4 duty is applied, the LCD drive waveform is depicted in the following figure.

Figure 14-2 LCD Drive Waveform When an LCD Panel of 1/4 Duty and 1/3 Bias is Applied

When an LCD panel of 1/6 duty is applied, the LCD drive waveform is depicted in the following figure.

Figure 14-3 LCD Drive Waveform When an LCD Panel of 1/6 Duty and 1/3 Bias is Applied

When an LCD panel of 1/8 duty is applied, the LCD drive waveform is depicted in the following figures.

Figure 14-4 LCD Drive Waveform When an LCD Panel of 1/8 Duty and 1/3 Bias is Applied

14.6. Registers

Table 14-6 LCD Control Register (LCDCtrl, 0x2C1E)

Table 14-7 Enable/Disable CLK3

Table 14-8 Register to Select Bias Mode

Table 14-9 LCD Waveform Voltage Configuration 1

Table 14-10 LCD Waveform Voltage Configuration 2

Table 14-11 SEG Control Registers (R/W)

0: to disable SEG signal output.

1: to enable SEG signal Output.

In the V98XX, the pins for SEG output are multiplexed by GPIO and analog input of M Channel. When these pins are configured for SEG output, they must be set to "input and output are disabled" for GPIO purpose. When the pins work as GPIO ports or for analog input of M Channel, they must be set to "disable SEG signal output" in these registers.

When bits LCDTYPE (bit[5:4] of LCDCtrl, 0x2C1E) are cleared, bit[1:0] of SegCtrl0 and SegCtrl1 are valid.

When bits LCDTYPE is set to 1, bit[1:0] of SegCtrl1 is valid, but bit[1:0] of SegCtrl0 is invalid.

When bits LCDTYPE is set to 2 or 3, bit[1:0] of SegCtrl1 and SegCtrl0 are invalid.

15. GPIO

In the V98XX there are 11 groups, P0~P10, 70 general-purpose input/output ports (GPIO) in total

of which:

- Ports of Group P0 are multiplexed by general input/output and JTAG interfaces. When the chip operates in metering mode, besides for general input/output, both P0.2 and P0.3 can be used to wake up the system from sleeping state. When the chip operates in debugging mode, these ports work as JTAG interfaces;
- Ports of Group P1 and P2 are multiplexed by general input/output and special functions. Both P1.3 and P1.4 can be used to wake up the system from sleeping state;
- Ports of Group P3 are multiplexed by general input/output and COM of the LCD driver;
- Ports of Group P4 and P5 are multiplexed by general input/output and COM or SEG output of the LCD driver;
- Ports of Group P6~P8 are multiplexed by general input/output and SEG output of the LCD driver;
- Ports of Group 9 are general-purpose input/output ports which has a communication rate of 200kbps when CLK1 frequency is 13.1072MHz. These ports are named *Fast IO* in this datasheet. These ports are multiplexed by general input/output and special functions;
- Ports of Group 10 are general-purpose input/output ports which has a communication rate of 200kbps when CLK1 frequency is 13.1072MHz. These ports are named *Fast IO* in this datasheet. These ports can be configured for transmitter data output and receiver data input of enhanced UART ports.

All the I/O ports have features:

- Ports of Group P0~P8 can be gate controlled simultaneously; Ports of Group P9 and P10 can be gate controlled independently;
- When POR/BOR, RSTn pin reset or WDT overflow event occurs, all ports will be reset to their default states: both input and output are disabled;
- In Sleep or Deep Sleep state, all ports hold their states;
- No pull-up or pull-down resistors are connected internally in all I/O ports.

15.1. P0

In Group P0 there are 4 ports, which are multiplexed by general-purpose input/output and JTAG interfaces.

When the level on the pin MODE1 is driven low, all ports of this group will work as JTAG interfaces. In this state, Port P0.0 is used for test data output (TDO); Port P0.1 is used for test data input (TDI); Port P0.2 is used for test mode select (TMS); Port P0.3 is used for test clock input (TCK). Ports of Group P1 and P2 are multiplexed by general input/output and special functions. Both
Ports of Group P1 and P2 are multiplexed by general input/output and COM of the LCD driver;
Ports of Group P3 are multiplexed by

When the level on the pin MODE1 is pulled high, all ports of this group will work as general-purpose input/output ports, and the input and output enable registers determine the state of each port. Set bit P0P8 (bit3 of PRCtrl0, 0x2D00) to 1 to gate control ports of Group P0~P8 to lower power consumption when these ports are not used. Besides, bit IOP0 (bit1 of IOWK, SFR 0xC9) determines both P0.2 and P0.3 to be used for IO wakeup inputs. See "[IO Wakeup](#page-67-0) " for details.

Figure 15-1 Architecture of P0.0

Figure 15-2 Architecture of P0.1/P0.2/P0.3

Table 15-1 P0 Output Enable Register (P0OE, 0x28A8)

Table 15-2 P0 Input Enable Register (P0IE, 0x28A9)

Table 15-3 P0 Output Data Register (P0OD, 0x28AA)

Table 15-4 P0 Input Data Register (P0ID, 0x28AB)

X: do not care.

the state change of an I/O port will lead to value variation of this register, which consumes more power. So to lower power consumption, it is recommended to disable data input if no need to read the input data.

15.2. P1

In Group P1 there are 5 ports, which are multiplexed by general-purpose input/output and special functions.

The function of each port can be configured via the dedicated special function register. When a port works as a general-purpose input/output port, the input and output enable registers determine its state. Set bit P0P8 (bit3 of PRCtrl0, 0x2D00) to 1 to gate control ports of Group P0~P8 to lower power consumption when these ports are not used. However, setting this bit to 1 after configuring these ports to work for special functions has no effect on its functions.

Figure 15-3 Architecture of Each Port of Group P1

If port P1.3 and/or P1.4 is set to "input enabled" before the system enters Sleep or Deep Sleep, the system will be woken up when a transition occurs to either port (either high-to-low or low-to-high, holding high and low level for at least 4 OSC clock cycles). See "IO Wakeup " for details.

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1: disable; 0: enable; X: do not care.

1: enable; 0: disable; X: do not care.

Table 15-7 P1 Output Data Register (P1OD, 0x28AE)

Table 15-8 P1 Input Data Register (P1ID, 0x28AF)

X: do not care.

When input is enabled, users can read the state of each I/O port via this register all the time, which is not affected by the special function of the port. But the state change of an I/O port will lead to value variation of this register, which consumes more power. So to lower power consumption, it is recommended to disable data input if no need to read the input data.

Table 15-9 P1.0 Special Function Register (P10FS, 0x28C4, R/W)

Table 15-10 P1.1 Special Function Register (P11FS, 0x28C5, R/W)

Table 15-11 P1.2 Special Function Register (P12FS, 0x28C6, R/W)

Table 15-12 P1.3 Special Function Register (P13FS, 0x28C7, R/W)

Table 15-13 P1.4 Special Function Register (P14FS, 0x28C8)

15.3. P2

In Group P2 there are 6, which are multiplexed by general-purpose input/output and special functions.

The function of each port can be configured via the dedicated special function register. When a port works as a general-purpose input/output port, the input and output enable registers determine its state. Set bit P0P8 (bit3 of PRCtrl0, 0x2D00) to 1 to gate control ports of Group P0~P8 to lower power consumption when these ports are not used. However, setting this bit to 1 after configuring these ports to work for special functions has no effect on its functions.

Figure 15-4 Architecture of Each Port of Group P2

1: disable; 0: enable; X: do not care.

Table 15-15 P2 Input Enable Register (P2IE, 0x28B1)

0x28B1, R/W, P2 Input Enable Register, P2IE

Table 15-17 P2 Input Data Register (P2ID, 0x28B3)

X: do not care.

When input is enabled, users can read the state of each I/O port via this register all the time, which is not affected by the special function of the port. But the state change of an I/O port will lead to value variation of this register, which consumes more power. So to lower power consumption, it is recommended to disable data input if no need to read the input data.

Table 15-18 P2.0 Special Function Register (P20FS, 0x28C9, R/W)

Table 15-19 P2.1 Special Function Register (P21FS, 0x28CA, R/W)

Table 15-20 P2.2 Special Function Register (P22FS, 0x28CB, R/W) (V98XX)

Table 15-21 P2.3 Special Function Register (P23FS, 0x28CC, R/W) (V98XX)

Table 15-22 P2.4 Special Function Register (P24FS, 0x28CD, R/W)

Table 15-23 P2.5 Special Function Register (P25FS, 0x28CE, R/W)

15.4. P3

In Group P3 there are 4 ports, which are multiplexed by general-purpose input/output andCOM.

When a port works as COM, in input and output enable registers the corresponding bit must be configured "input disabled, output disabled".

When a port works as a general-purpose input/output port, the SEG/COM driver in the LCD driver must be disabled (bit7 of LCDCtrl, 0x2C1E). Set bit P0P8 (bit3 of PRCtrl0, 0x2D00) to 1 to gate control ports of Group P0~P8 to lower power consumption when these ports are not used.

Figure 15-5 Architecture of Each Port of Group P3

Table 15-25 P3 Input Enable Register (P3IE, 0x28B5)

Table 15-26 P3 Output Data Register (P3OD, 0x28B6)

Table 15-27 P3 Input Data Register (P3ID, 0x28B7)

0x28B7, R/W, P3 Input Data Register, P3ID

15.5. P4

In Group P4 there are 8 ports, which are multiplexed by General-Purpose Input/Output (GPIO) and signal output of the LCD driver.

When LCDTYPE=0 Ports P4.0~P4.7 can be configured to be multiplexed by SEG output and generalpurpose input/output. When LCDTYPE=1/2/3, P4.0~ P4.7 are multiplexed by COM output and generalpurpose input/output.

When a port works as backplanes or SEG output of the LCD driver, in input and output enable registers, P4OE (0x28B8) and P4IE (0x28B9), the corresponding bit must be configured "input disabled, output disabled".

When a port works as a general-purpose input/output port, the SEG output on the corresponding port must be disabled and input and output enable registers determine its state. Set bit P0P8 (bit3 of PRCtrl0, 0x2D00) to 1 to gate control ports of Group $P0~P8$ to lower power consumption when these ports are not used.

Figure 15-6 Architecture of Each Port of Group P4

Table 15-28 P4 Output Enable Register (P4OE, 0x28B8)

1: disable; 0: enable; X: do not care.

Table 15-29 P4 Input Enable Register (P4IE, 0x28B9)

Table 15-30 P4 Output Data Register (P4OD, 0x28BA)

Table 15-31 P4 Input Data Register (P4ID, 0x28BB)

X: do not care.

When input is enabled, users can read the state of each I/O port via this register all the time, which is not affected by the special function of the port. But the state change of an I/O port will lead to value variation of this register, which consumes more power. So to lower power consumption, it is recommended to disable data input if no need to read the input data.

15.6. P5

In Group P5 there are 8 ports, which are multiplexed by general-purpose input/output and COM of the LCD driver.

Ports P5.0 and P5.1 can be configured to be multiplexed by SEG output and general-purpose input/output; when LCDTYPE=0 or 1, when LCDTYPE=2or3, and ports P5.2-P5.7 are multiplexed by SEG output and general-purpose input/output.

When a port works as COM or SEG output of the LCD driver, in input and output enable registers, the corresponding bit must be configured "input disabled, output disabled".

When a port works as a general-purpose input/output port, SEG or COM output on the corresponding port must be disabled, and input and output enable registers determine its state. Set bit P0P8 (bit3 of PRCtrl0, 0x2D00) to 1 to gate control ports of Group P0~P8 to lower power consumption when these

ports are not used.

Figure 15-7 Architecture of Each Port of Group P5

Table 15-33 P5 Input Enable Register (P5IE, 0x28BD)

Table 15-34 P5 Output Data Register (P5OD, 0x28BE)

Table 15-35 P5 Input Data Register (P5ID, 0x28BF)

0x28BF, R/W, P5 Input Data Register, P5ID

When input is enabled, users can read the state of each I/O port via this register all the time, which is not affected by the special function of the port. But the state change of an I/O port will lead to value variation of this register, which consumes more power. So to lower power consumption, it is recommended to disable data input if no need to read the input data.

15.7. P6

In Group P6 there are 8 ports, which are multiplexed by general-purpose input/output and SEG output of the LCD driver.

When a port works as SEG output of the LCD driver, in input and output enable registers, the corresponding bit must be configured "input disabled, output disabled".

When a port works as a general-purpose input/output port, SEG output on the corresponding port must be disabled, and input and output enable registers determine its state. Set bit P0P8 (bit3 of PRCtrl0, 0x2D00) to 1 to gate control ports of Group P0~P8 to lower power consumption when these ports are not used.

Figure 15-8 Architecture of Each Port of Group P6

15.8. P7

In Group P7 there are 8 ports, which are multiplexed by general-purpose input/output and SEG output of the LCD driver.

When a port works as SEG output of the LCD driver, in input and output enable registers the corresponding bit must be configured "input disabled, output disabled".

When a port works as a general-purpose input/output port, the SEG output on the corresponding ports must be disabled and input and output enable registers determine its state. Set bit P0P8 (bit3 of PRCtrl0, 0x2D00) to 1 to gate control ports of Group P0~P8 to lower power consumption when these ports are

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not used.

Figure 15-9 Architecture of Each Port of Group P7

Table 15-40 P7 Output Enable Register (P7OE, 0x28D5)

Table 15-41 P7 Input Enable Register (P7IE, 0x28D6)

Table 15-42 P7 Output Data Register (P7OD, 0x28D7)

Table 15-43 P7 Input Data Register (P7ID, 0x28D8)

0x28D8, R/W, P7 Input Data Register, P7ID

When input is enabled, users can read the state of each I/O port via this register all the time, which is not affected by the special function of the port. But the state change of an I/O port will lead to value variation of this register, which consumes more power. So to lower power consumption, it is recommended to disable data input if no need to read the input data.

15.9. P8

In Group P8 there are 3 ports, which are multiplexed by general-purpose input/output and SEG output of the LCD driver.

When a port works as SEG output of the LCD driver, in input and output enable registers, the corresponding bit must be configured "input disabled, output disabled".

When a port works as a general-purpose input/output port, the SEG output on the corresponding port must be disabled, and input/output enable registers determine its state. Set bit P0P8 (bit3 of PRCtrl0, 0x2D00) to 1 to gate control ports of Group P0~P8 to lower power consumption when these ports are not used.

Figure 15-10 Architecture of Each Port of Group P8

1: disable; 0: enable; X: do not care.

Table 15-45 P8 Input Enable Register (P8IE, 0x28DA)

Table 15-46 P8 Output Data Register (P8OD, 0x28DB)

Table 15-47 P8 Input Data Register (P8ID, 0x28DC)

X: do not care.

When input is enabled, users can read the state of each I/O port via this register all the time, which is not affected by the special function of the port. But the state change of an I/O port will lead to value variation of this register, which consumes more power. So to lower power consumption, it is recommended to disable data input if no need to read the input data.

15.10. P9

In Group P9 there are 8 ports, which are multiplexed by general-purpose input/output, special functions and, P1.2 and P1.3 can be used GPSI.

When the ports work as general-purpose input/output ports, When CLK1 frequency is 13.1072MHz, the communication rate of these ports is 200kbps; input and output enable registers determine their states. But when a reference pulse of exact one second width is input to the port P9.1, the input of this port is enabled automatically.

The function of each port can be configured via the register P9FS (SFR 0xAD).

When bit GPSI (bit6 of PRCtrl0, 0x2D00) is set to 1, port P9.1 and P9.2 are used for serial data and clock delivery for general-purpose serial interface (GPSI). In this condition, P9.1 must be set to "input enabled" The P9.1 output is determined by the data on SDA; and P9.2 is set to "output enabled" automatically,

Don't need to configure P9.1 and P9.2 output register.

The port P9.0 can be used for SEG output of the LCD driver. When the port works as SEG output of the LCD driver, in input and output enable registers, the corresponding bit must be configured "input disabled, output disabled".

Set bit P9 (bit4 of PRCtrl0, 0x2D00) to 1 to gate control ports of Group P9 to lower power consumption.

Figure 15-11 Architecture of Each Port of Group P9

Table 15-48 P9 Output Enable Register (P9OE, SFR 0xA4)

Table 15-49 P9 Input Enable Register (P9IE, SFR 0xA5)

When input is enabled, users can read the state of each I/O port via this register all the time, which is not affected by the special function of the port. But the state change of an I/O port will lead to value variation of this register, which consumes more power. So to lower power consumption, it is recommended to disable data input if no need to read the input data.

Default 0 0 0 0 0 0 0 0

Table 15-52 P9 Special Function Register (P9FS, SFR 0xAD)

SFR 0xAD, R/W, P9 Special Function Register, P9FS

15.11. P10

In Group P10 there are 8 ports, which are multiplexed by general-purpose input/output and enhanced UART interfaces. the port P10.0 is used for data input and output of EUART1. the port P10.1 is used for data output of EUART2, and the port P10.2 is used for data input of EUART2.

When the ports work as general-purpose input/output ports, the ports of Group P10 have the same feature with those of Group P9. They are accessed in a fast mode. When CLK1 frequency is 13.1072MHz, the communication rate of these ports is 200kbps. Input and output enable registers determine their states.

When the bit ENABLE (bit0 of CFGA, 0x2A05) is set to 1, the port P10.0 is used for data input and output of EUART1. In this condition, the output of this port is enabled automatically, and the input of this port is determined by the register P10IE (SFR 0xAA). When the bit ENABLE (bit0 of CFGB, 0x2B05) is set to 1, the port P10.1 is used for data output of EUART2, and the port P10.2 is used for data input of EUART2.In this condition, the output or input of the ports are determined by registers P10OE (SFR 0xA9) and P10IE (SFR 0xAA). 1: TAO, to input/output the signals for Timer A Compare/Capture Mod

1: TAO, to input/output the signals for Timer A Compare/Capture Mod

0: general-purpose input/output port in fast mode.

1. THE Trimeraces. the port P10.

Set bit P10 (bit5 of PRCtrl0, 0x2D00) to 1 to gate control ports of Group P10 to lower power consumption when these ports are not used.

Figure 15-12 Architecture of Each Port of Group P10

Table 15-53 P10 Output Enable Register (P10OE, SFR 0xA9)

Table 15-54 P10 Input Enable Register (P10IE, SFR 0xAA)

1: enable; 0: disable; X: do not care.

Table 15-55 P10 Output Data Register (P10OD, SFR 0xAB)

Table 15-56 P10 Input Data Register (P10ID, SFR 0xAC)

SFR 0xAC, R/W, P10 Input Data Register, P10ID

Table 15-57 Configuration for EUART Communication

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implementation to fulfill this requirement.

16. Watchdog Timer (WDT)

In the V98XX the embedded 16-bit watchdog timer (WDT) counting pulses of the 32kHz RC clock. When the program gets stuck somewhere, the timer overflows and reset the system to cause the program restart from the beginning.

16.1. Clock for WDT

In the V98XX, CLK4, sourced by the 32kHz RC clock, provides clock pulse for the WDT. RC clock cannot be disabled until the chip is powered off, but CLK4 is enabled or disabled together with CLK1. When CLK4 (together with CLK1) is disabled, which means the system enters Sleep or Deep Sleep state, the WDT stops running. When the system is woken up by IO/RTC wakeup event or power recovery, the WDT restarts counting from zero.

Table 16-1 Enable/Disable CLK4

16.2. Clearing WDT

When IO/RTC wakeup event, power recovery event, POR/BOR or RSTn pin reset occurs, the WDT is reset, and its counts are cleared. When the reset signal is released, the WDT starts counting from zero again.

Users can write a program to clear the WDT counts to prevent the WDT from resetting the system when its counts overflow: write 0xA5 to the register WDTEN (SFR 0xCE) and then 0x5A to the register WDTCLR (SFR 0xCF) continuously to clear the WDT counts. Immediately the WDT is cleared, it will restart counting pulses from zero.

16.3. WDT Overflow Reset

Initially, the WDT starts counting pulses from 0. If the counts are not cleared when the WDT counts to

 (3×2^{14}) , that is about 1.5s, the WDT overflows, a reset pulse of 8 RC clock periods $(8/\text{f}_{\text{RC}})$ width is output, and the system is reset to default state. After the reset, the WDT starts counting from (-2^{14}) , and then, if the WDT is still not cleared, the WDT will overflow again when it counts to (3×2^{14}) , that is about 2s.

When the WDT overflow reset occurs, the flag bit POR (bit5 of Systate, SFR 0xA1) is set to 1. When other reset events, not POR/BOR or RSTn pin reset, occurs, this bit will be cleared. In debugging mode, this reset event is masked.

A WDT overflow event can reset all circuits except the RTC calibration registers, RTC timing registers, IRAM and XRAM.

Figure 16-1 WDT Overflow Reset

17. Real-Time Clock (RTC)

In the V98XX, the RTC has features as follows:

- counting the pulses of the 32.768kHz OSC clock;
- calibrating crystal frequency over temperature variation;
- calibrated pulse output every exact one second;
- timing error less than 5ppm over operating temperature range;
- providing real-time clock and calendar, and adjusting the date for leap year automatically.

In the RTC, the registers for calibration and timing cannot be reset by any reset event; and the other registers will be reset to their default states when POR/BOR, RSTn pin reset or WDT overflow event occurs.

In Sleep state, the RTC keeps running and can be configured to wake up the system at an programmable interval of 1 day, 1 hour, 1 minute, 1~64 seconds, 500ms, 250ms, 125ms or 62.5ms. The wakeup signal will hold 8 OSC clock periods.

Figure 17-1 Architecture of RTC

17.1. Reading and Writing of RTC Registers

17.1.1. Writing of RTC

In the V98XX, the registers INTRTC (SFR 0x96), RTC calibration registers and RTC timing registers are protected from writing.

The MCU must write of these registers following exact steps as:

- 1. writing 0x96 to the register RTCPEN to enable writing of the register RTCPWD;
- 2. writing 0x57 to the register RTCPWD to enable writing of INTRTC (SFR 0x96), RTC calibration registers and RTC timing registers;
- 3. After 5 OSC clock cycles, configuring the registers INTRTC (SFR 0x96), RTC calibration registers and RTC timing registers;
- 4. After 5 OSC clock cycles, writing 0x96 to the register RTCPEN to enable writing of the register RTCPWD;
- 5. Writing 0x56 to the register RTCPWD to disable writing of the registers INTRTC (SFR 0x96), RTC calibration registers and RTC timing registers. 5 OSC clock cycles later, the contents of the registers are activated. A second write operation can be done to these registers only when the last configuration is completed. writing 0x96 to the register RTCPEN to enable writing of the register RTCPWD;
writing 0x57 to the register RTCPWD to enable writing of INTRTC (SFR 0x96), RTC call
registers and RTC timing registers;
RTE ching registers;
RT

17.1.2. Reading of RTC

To read the timing registers, the MCU must read the register RDRTC (SFR 0xDA) firstly, waits no less than 5 OSC clock cycles till the contents of the RTC timing registers are latched, and then read the timing registers for the time information.

But the MCU can read the calibration registers directly.

17.2. Timing

When the chip is powered on, the RTC starts to run, and it keeps on running until the system is powered off.

If the timing registers are not configured, the RTC runs from a random time; otherwise, the RTC runs from the preset time.

17.3. RTC Interrupts

In the V98XX, the RTC can trigger two interrupt events if they are enabled: illegal data interrupt and pulse output interrupt per second.

17.3.1. RTC Illegal Data Interrupt

When the RTC illegal data interrupt is enabled ($EA=1$, $EIE.2=1$ and $ExInt4IE.0=1$), an illegal data interrupt will be triggered when:

- The MCU writes of the registers INTRTC (SFR 0x96), RTC calibration registers and RTC timing registers when they are still being protected from writing;
- The MCU writes the contents in an illegal format into the registers INTRTC (SFR 0x96), RTC calibration registers and RTC timing registers when the writing operation is enabled;

The contents of the timing registers are in binary-coded decimal (BCD) format, so 0xF is not considered as an illegal data.

In both circumstances, the RTC timing registers will hold the contents.

 Data error caused by the system error occurs during the operation. In this circumstance, the MCU must configure all RTC timing registers **consecutively** immediately the writing operation is enabled, and then disable the writing operation to activate the correction.

17.3.2. Pulse Output Interrupt per Second

When EA=1, EIE.1=1 and ExInt3IE.6=1, the pulse output interrupt per second is enabled, and the RTC will output pulses of 1 second width to the MCU to trigger interrupts.

17.4. PLL Counter

There is a 24-bit PLL counter in the V98XX. It can work as a PLL clock divider or a counter, which is determined by the register PLLCNTST (SFR 0xDE).

When the register PLLCNTST (SFR 0xDE) is set to 0x00, the PLL counter works as a divider. In this mode, the PLL counter counts from 0 and increments by 1 every OSC clock cycle. When it counts to the pre-set value of the PLL clock divider registers, this counter will be cleared, output pulses at a frequency proportional to the divided PLL clock frequency from Pin31/Pin30/Pin43, and then the counter will start recounting. The frequency of the pulse can be calculated as follows: In illegal data.

Solution criation and by the system error occurs unith of the contents.

Data error caused by the system error cocurs unith g the operation. In this circumstance, the

must configure all RTC timing regis

$$
f_{\text{DIV}} = \frac{f_{\text{MCU}}}{2 \times (\text{TH} + 1)}
$$
 Equation 17-1

where,

- *fDIV*, the frequency of the pulse, Hz;
- *f_{MCU*}, the MCU clock frequency (Hz), which has a relationship with the OSC clock frequency (fosc)as follows:

 $f_{MC11} = K \times f_{C2}$

Equation 17-2

where, *K* is a coefficient, equal to 100/200/400; when the theoretical *fMCU* is 13.1072MHz, *K* is 400.

 TH, the preset value of the PLL divider registers (DIVTHH/DIVTHM/DIVTHL). In the default state, the value of *TH* is 0, so the MCU clock frequency is divided by 2. The MCU clock frequency can be divided by up to 2^{25} .

When the register PLLCNTST (SFR 0xDE) is configured to 0x01, the PLL counter works as a counter.

When the first low-to-high transition of a reference pulse of exact 1 second width input on Pin89 (SDSP) is detected, which will configure the register to 0x02 automatically, the counter starts counting from zero. And then, when the second low-to-high transition of the reference pulse input is detected, the register PLLCNTST (SFR 0xDE) is configured to 0x03 automatically, the PLL counter stops running, and the current counts is transferred to the PLL clock divider registers to calculate the actual frequency of the pulse.

17.5. Calibrating RTC

In the V98XX, the MCU can use the PLL counter or the internal counter of the RTC to calibrate the RTC.

17.5.1. Calibrating Pulse Frequency of PLL Counter

The internal counter of the RTC counts the clock pulse provided by the OSC clock. From the $1st$ to 29th second, the RTC outputs pulses every 32768 counts; in the 30th second, the RTC outputs a pulse when the counts are [32768-(C-1)] (C is the value of the calibration register in decimal) to average the width of pulses in 30 seconds to be 1 second each. So the RTC cannot calibrate timing error in real time by itself. But when the PLLCNTST is used to output a pulse of exact 1 second width (PPS) every second, the error of the pulse width can be corrected in real time. Because both RTC and PLLCNTST are pulsed by the OSC clock, so users can calibrate the RTC timing via correcting the PPS width error. **7.5.1. Calibrati[n](#page-238-1)[g](#page-237-1) Pulse Frequency of PLL Counter**

ne internal counter of the RTC counts the clock pulse provided by the OSC clock. From the 1st

nond, the RTC cutputs pulses every 32768 counts; in the 30th second,

The relationship of the value of C (in decimal) and actual OSC clock frequency (f_{osc}) is as follows:

$$
C - 1 = 30 \times (32768 - f_{\text{OSC}})
$$

Equation 17-3

According to Equation 17-1 and Equation 17-2, to calibrate the pulse frequency of the PLL counter (f_{DIV}) to be 1Hz, the nominal *TH* and actual *TH'* has a relationship as follows:

TH-TH' = ΔTH =
$$
\frac{K}{2}
$$
 × (32768 - f_{OSC}) = 200 × (32768 - f_{OSC}) *Equation 17-4*

where, *TH* is the value for nominal fosc, namely 32768Hz; *TH'* is the value for actual fosc.

According to Equation 17-3 and Equation 17-4, a relationship between *ΔTH* and *C* is obtained:

$$
\frac{\Delta TH}{C-1} = \frac{200}{30}
$$
 Equation 17-5

According to Equation 17-5, users can calibrate the RTC timing via correcting the PPS width error.

17.5.2. Calibrating Divided Pulse Frequency of PLL Counter

When Pin89 is used to input a reference pulse of exact 1 second width, the PLL counter is used to capture and measure the width of this input signal, which can be used to calibrate the RTC. The calibration steps are as follows:

1. The MCU writes 0x01 to the register PLLCNTST (SFR 0xDE) to clear the PLL counter, and the PLL counter works as a counter;

- 2. When the first high-to-low transition of the reference pulse of exact 1 second width is detected, which will configure the register to 0x02 automatically, the counter starts counting from zero.
- 3. When the second low-to-high transition of the reference pulse is detected, the register PLLCNTST (SFR 0xDE) is configured to 0x03 automatically, the PLL counter stops running, and the current counts are transferred to the PLL clock divider registers as the value of *TH* to generate pulses of exact 1 second width to calibrate the crystal frequency using the following equation:

 $\frac{1}{\mathsf{K}} \times (\mathsf{TH} + 1)$ fosc = $\frac{2}{16}$ Equation 17-6

When the theoretical frequency of the MCU (*fMCU*) is 13.1072MHz, the relationship of *C*, the value to be written to the calibration register, and *TH* in the preceding equation is as follows:

$$
C - 1 = \frac{30}{200} \times (TH + 1) - 32768 \times 30
$$

Equation 17-7

17.5.3. Crystal Frequency-Temperature Curve

The crystal frequency is affected by the ambient temperature. In the V98XX there is a temperature measurement circuit. Users can measure the crystal frequency in different ambient temperatures and calculate the values to be written to the calibration register (C) according to the following steps to calibrate the crystal frequency to be exact 32768Hz at different temperatures, and then tabulate them according to the relationship for table look-at:

- 4. Set the reference crystal frequencies in different ambient temperature, such as 32768Hz;
- 5. Write 0x01 to the calibration registers and measure the actual crystal frequency (f_{OSC}) using a frequency meter via Pin96 in different ambient temperature, and calculate the value of *C'* (*C'=C-1*) using the following equation:

$$
C = \frac{f_{\text{OSC}} - 32768}{32768} \times 1000000 / (\frac{1}{32768} \times \frac{1}{30} \times 1000000) = 30 \times (f_{\text{OSC}} - 32768)
$$

Equation 17-8

Where, $\frac{1}{32768} \times \frac{1}{30} \times 1000000$ $\frac{1}{200} \times \frac{1}{20} \times 1000000$, equal to 1.02ppm, represents the calibration accuracy of the RTC of

average one second in the 30 seconds; and $\frac{f_{\text{OSC}}-32768}{32768} \times 1000000$ represents the quantity of the crystal

frequency to be calibrated in unit of ppm.

Figure 17-3 Crystal Frequency-Temperature Curve

17.6. Registers

In the RTC, the registers for calibration and timing cannot be reset by any reset event; and the other registers will be reset when POR/BOR, RSTn pin reset or WDT overflow event occurs.

Table 17-2 RTC Password Register (RTCPWD, SFR 0x97) $\overline{\Gamma}$

Table 17-3 RTC Wakeup Interval Register (INTRTC, SFR 0x96)

Configure this register for the interval at which the RTC will wake up the system from Sleep state. The wakeup signal holds 8 OSC clock periods.

Table 17-4 RTC Seconds Wake-up Interval Configuration Register (SECINT, SFR 0xDF)

Table 17-5 Flag Bit of RTC Wakeup Event

T

Table 17-6 RTC Calibration Registers (RTCCH/RTCCL, SFR 0x94/0x95)

Table 17-7 RTC Data Reading Enable Register (RDRTC, SFR 0xDA)

Table 17-8 PLL Clock Divider Registers (DIVTHH/DIVTHM/DIVTHL, SFR 0xDB/0xDC/0xDD)

Table 17-9 PLL Counter State Register (PLLCNTST, SFR 0xDE)

The time and calendar information is obtained by reading the appropriate register bytes. The contents of the timing registers, except the register for day of week configuration, are in binary-coded decimal (BCD) format, of which bit7~bit4 represents the tens digit of the time and calendar, and bit3~bit0 represents the units digit of the time and calendar; for example, 0b1000011 in the register RTCSC represents 43 seconds. The RTC can provide second, hour, day, week, month and year information. As such, both RTCSC (seconds) and RTCMiC (minutes) range 0~59, RTCHC (hour) ranges 00~24, RTCDC (day) ranges $1 \sim 31$, RTCMoC (month) ranges $1 \sim 12$ and RTCYC (year) ranges $0 \sim 99$.

Table 17-10 RTC Timing Registers

Users must set the day of week information for one date; for example, set the date 1st Jan. 2010 to be Friday, and the RTC will determine the date 2nd, Jan., 2010 to be Saturday automatically. 0b000: Sunday; 0b001: Monday; 0b010: Tuesday; 0b011: Wednesday; 0b100: Thursday; 0b101: Friday; 0b110: Saturday; 0b111: Invalid data.

For the year information, only the tens and units digits of the year need to be configured in the register RTCYC; for example, 0b00010000 represents the year 2010.

Users should set the information of year, month, day, hour, minute, second, and week according to certain sequence at one time. It will fail if set up separately.

18. Registers

18.1. Analog Control Registers

In the V98XX, analog control registers are located at addresses 0x2858~0x2868. The registers are readable and writable. When POR/BOR, RSTn pin reset or WDT overflow reset occurs, the analog control registers will be reset to their default states. In this section, the default values are in decimal form unless otherwise noted.

The register located at address 0x285F must be configured to its default values for proper operation.

Users can read of bytes located at addresses 0x300C~0x3059 to obtain the recommended configuration of the analog registers, and write them to the analog registers.

Table 18-1 ADC Control Register 0 (CtrlADC0, 0x2858)

Table 18-2 ADC Control Register 1 (CtrlADC1, 0x2859)

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Table 18-3 ADC Control Register 2 (CtrlADC2, 0x285A)

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Table 18-4 ADC Control Register 3 (CtrlADC3, 0x285B)

Table 18-5 Battery Discharge Control Register (CtrlBAT, 0x285C)

Table 18-6 ADC Control Register 4 (CtrlADC4, 0x285D)

Table 18-7 LCD Driver Voltage Control Register (CtrlLCDV, 0x285E)

Table 18-8 Crystal Control Register 1 (CtrlCry1, 0x2860)

Table 18-9 Crystal Control Register 2 (CtrlCry2, 0x2861)

Table 18-10 BandGap Control Register (CtrlBGP, 0x2862)

Table 18-11 ADC Control Register 5 (CtrlADC5, 0x2863)

SegCtrl4 (0x2C23) must be cleared to disable the SEG output on the pins.

Table 18-12 ADC Control Register 6 (CtrlADC6, 0x2864)

Table 18-13 Channel M Control Register (CtrlM, 0x2865)

Table 18-14 LDO Control Register (CtrlLDO, 0x2866)

Table 18-15 Clock Control Register (CtrlCLK, 0x2867)

Table 18-16 PLL Control Register (CtrlPLL, 0x2868)

Table 18-17 Analog Circuits State Register (ANState, 0x286B)

18.2. Metering Control Registers

When POR/BOR, RSTn pin reset or WDT overflow reset occurs, all metering control registers are reset to their default states.

All the default values in this section are in decimal form if not specifically noted.

Table 18-19 PM Control Register 2 (PMCtrl2, 0x2879)

Table 18-20 PM Control Register 3 (PMCtrl3, 0x287A)

Table 18-21 Phase Compensation Control Register 1 (PHCCtrl1, 0x287B)

Table 18-22 Phase Compensation Control Register 2 (PHCCtrl2, 0x287C)

0x287C, R/W, Phase Compensation Control Register 2, PHCCtrl2

Table 18-23 PM Control Register 4 (PMCtrl4, 0x287D)

Table 18-24 CF Pulse Output Control Register (CFCtrl, 0x287E)

Table 18-25 No-Load Detection Indication Register (CRPST, 0x287F)

Table 18-26 Current Detection Control Register (IDET, 0x2886)

18.3. Metering Data Registers

When POR/BOR, RSTn pin reset or WDT overflow reset occurs, all metering data registers are reset to their default states.

All metering data registers are readable and writable (R/W). But users must not write of these registers to avoid unexpected results.

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All the default values in this section are in decimal form if not specifically noted. All the time for updating and settling listed in the tables is appropriate for 50Hz power grid and *fMTCLK*=3.2768MHz. When the frequency for metering architecture (*fMTCLK*) is divided by K, the time for updating and settling must be K times of that for 3.2768MHz. In 60Hz power grid, the time for updating and settling is 1.2 times of that for 50Hz power grid.

Table 18-27 Signal Waveform Registers (R/W)

Table 18-28 Power and RMS Registers (R/W)

Table 18-29 Energy Accumulators and Energy Pulse Counters (R/W)

The energy accumulators are of actual 42-bit length. But only the higher 32 bits are readable; and only the higher 32 bits are valid for write operation and the 10 least significant bits are padded with 0s in write operation.

When MTCLK frequency is 3.2768MHz, 1.6384MHz or 819.2kHz, the energy accumulation frequency is 12800Hz; when MTCLK frequency is 32768Hz, the energy accumulation frequency is 2979Hz.

When CF pulse output is enabled, the overflow frequency of the energy accumulators is twice of CF pulse output frequency. The reading of the energy pulse counter is twice of the number of the output CF pulses.

Table 18-30 Line Frequency Register (DATAFREQ, 0x10FD)

This register is in the form of 16-bit unsigned.

When MTCLK frequency is 3.2768MHz, the content is updated in 320ms and settled in 500ms. The frequency measurement resolution is up to 0.05Hz/lsb, and the measurement scale is over the range of 35~75Hz.

Table 18-31 Data Registers for Channel M

18.4. Calibration Registers

When POR/BOR, RSTn pin reset or WDT overflow reset occurs, all calibration registers are reset to their default states.

All the default values in this section are in decimal form if not specifically noted.

Table 18-32 Registers for Gain Calibration (R/W)

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Table 18-33 Registers for Power Offset Calibration (R/W)

Table 18-34 Band-pass Filter Coefficient Register (0x10EF, R/W)

When MTCLK frequency is lowered to 819.2kHz, the sampling frequency of the enabled band-pass filter in the RMS calculation circuit is changed to 800Hz and the center frequency is changed to 12.5Hz, which has a greater attenuation on 50Hz signals and will reduce the accuracy of the RMS calculation and line frequency measurement. So, if MTCLK frequency is reduced to 819.2kHz, users must disable energy accumulation, CF pulse output and no-load detection, and then configure this register to 0x911D3C9C. When MTCLK frequency is reinstated to 3.2768MHz, this register must be set to its default value.

Table 18-35 Energy Threshold Registers and Constant Power Register (R/W)

The energy accumulators are of actual 42-bit length, but the threshold registers for energy-to-pulse conversion are of 32-bit length. So, the threshold registers will be padded with a string of 10 0s on the right to work as 42-bit registers for computation.

There is an anti-creeping accumulator in the no-load detection circuit. When no-load detection is enabled, 1s are accumulated in this register constantly. When MTCLK frequency is 3.2768MHz, 1.6384MHz or 819.2kHz, the accumulation frequency is 12800Hz; and when MTCLK frequency is 32768Hz, the accumulation frequency is 2979Hz.

When no-load detection is enabled, the circuit compares the rate at which the anti-creeping accumulator increments by 1s to that at which the energy accumulators accumulate E1/E2 power or the preset constant. If the energy accumulator overflows sooner, the anti-creeping accumulator is cleared, and E1 or E2 path starts to metering energy. Otherwise, the energy accumulator in E1 or E2 path is cleared, and the path enters creeping state. Users can read bit7 or bit6 of register CRPST (0x287F) to detect the state of the path. 10FC **DATACP** To set a constant for active energy accumulation in $\begin{bmatrix} 32 \text{-bit} & 22 \text{ bit} \\ 61 \text{ path.} \end{bmatrix}$

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19. Outline Dimensions

V9811S/V9811A

V9821/V9821S

